



Integrated Analog Front-End for Pulse Oximeters

Check for Samples: AFE4490

FEATURES

- Fully-Integrated Analog Front-End for Pulse Oximeter Applications:
 - Flexible Pulse Sequencing and Timing Control
- Transmit:
 - Integrated LED Driver (H-Bridge or Push/Pull)
 - 110-dB Dynamic Range Across Full Range (Enables Low Noise at Low LED Current)
 - LED Current:
 - Programmable Ranges of 50 mA, 75 mA, 100 mA, 150 mA, and 200 mA, Each with 8-Bit Current Resolution
 - Low Power:
 - 100 μA + Average LED Current
 - LED On-Time Programmability from (50 μs + Settle Time) to 4 ms
 - Independent LED2 and LED1 Current Reference
- Receive Channel with High Dynamic Range:
 - Input-Referred Noise:
 - 13 pA_{RMS} (0.1-Hz to 5-Hz Bandwidth)
 - 13.5 Noise-Free Bits (0.1 Hz to 5 Hz)
 - Analog Ambient Cancellation Scheme with Selectable 1-μA to 10-μA Ambient Current
 - Low Power: < 2.3 mA at 3.0-V Supply
 - Rx Sample Time: 50 µs to 250 µs
 - I-V Amplifier with Seven Separate LED2 and LED1 Programmable Feedback R and C Settings
 - Integrated Digital Ambient Estimation and Subtraction
- Integrated Fault Diagnostics:
 - Photodiode and LED Open and Short Detection
 - Cable On/Off Detection
- Supplies:
 - Rx = 2.0 V to 3.6 V
 - Tx = 3.0 V or 5.25 V

- Package: Compact QFN-40 (6 mm × 6 mm)
- Specified Temperature Range: –40°C to +85°C

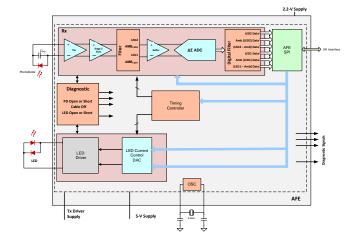
APPLICATIONS

- Medical Pulse Oximeter Applications
- Industrial Photometry Applications

DESCRIPTION

The AFE4490 is a fully-integrated analog front-end (AFE) that is ideally suited for pulse-oximeter applications. The device consists of a low-noise receiver channel with a 22-bit analog-to-digital converter (ADC), an LED transmit section, and diagnostics for sensor and LED fault detection. The AFE4490 is a very configurable timing controller. This flexibility enables the user to have complete control of the device timing characteristics. To ease clocking requirements and provide a low-jitter clock to the AFE4490, an oscillator is also integrated that functions from an external crystal. The device communicates to an external microcontroller or host processor using an SPI™ interface.

The AFE4490 is a complete AFE solution packaged in a single, compact QFN-40 package (6 mm \times 6 mm) and is specified over the operating temperature range of -40° C to $+85^{\circ}$ C.





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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

FAMILY AND ORDERING INFORMATION

PRODUCT	PACKAGE-LEAD	LED DRIVE CONFIGURATION	LED DRIVE CURRENT (mA, max)	POWER SUPPLY (V)	OPERATING TEMPERATURE RANGE
AFE4490	QFN-40	Bridge, push-pull	50, 75, 100, 150, and 200	3 to 5.25	-40°C to +85°C
AFE4400	QFN-40	Bridge, push-pull	50	3 to 3.6	0°C to +70°C

ABSOLUTE MAXIMUM RATINGS(1)

Over operating free-air temperature range, unless otherwise noted.

		VALUE	UNIT
AVDD to AVSS		-0.3 to +7	V
DVDD to DGND			V
AGND to DGND		-0.3 to +0.3	V
Analog input to AVSS		AVSS - 0.3 to AVDD + 0.3	V
Digital input to DVDD		DVSS - 0.3 to DVDD + 0.3	V
Input current to any pin exc	cept supply pins ⁽²⁾	±7	mA
Innut ourrent	Momentary	±50	mA
Input current	Continuous	±7	mA
Operating temperature ran	ge	-40 to +85	°C
Storage temperature range	e, T _{stg}	-60 to +150	°C
Maximum junction tempera	iture, T _J	+125	°C
Electrostatic discharge	Human body model (HBM) JEDEC standard 22, test method A114-C.01, all pins	±1000	V
(ESD) ratings	Charged device model (CDM) JEDEC standard 22, test method C101, all pins	±500	V

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

THERMAL INFORMATION

		AFE4490	
	THERMAL METRIC ⁽¹⁾	RHA (QFN)	UNITS
		40 PINS	
θ_{JA}	Junction-to-ambient thermal resistance	35	
θ_{JCtop}	Junction-to-case (top) thermal resistance	31	
θ_{JB}	Junction-to-board thermal resistance	26	0000
ΨЈТ	Junction-to-top characterization parameter	0.1	°C/W
ΨЈВ	Junction-to-board characterization parameter	N/A	
θ_{JCbot}	Junction-to-case (bottom) thermal resistance	N/A	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

⁽²⁾ Input terminals are diode-clamped to the power-supply rails. Input signals that can swing beyond the supply rails must be current-limited to 10 mA or less.

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RECOMMENDED OPERATING CONDITIONS

Over operating free-air temperature range, unless otherwise noted.

	PARAMETER		VALUE	UNIT
SUPPLIES				
RX_ANA_SUP	AFE analog supply		2.0 to 3.6	V
RX_DIG_SUP	AFE digital supply		2.0 to 3.6	V
TX_CTRL_SUP	Transmit controller supply		3.0 to 5.25	V
1.ED DDV 011D	Toward I ED diversion	H-bridge configuration	[3.0 or (1.4 + V _{LED} + V _{CABLE}) ⁽¹⁾ (2), whichever is greater] to 5.25	٧
LED_DRV_SUP	Transmit LED driver supply Common anode [3.0 or (1)	[3.0 or (1.3 + V _{LED} + V _{CABLE}) ⁽¹⁾⁽²⁾ , whichever is greater] to 5.25	٧	
	Difference between LED_DRV_	_SUP and TX_CTRL_SUP	-0.3 to +0.3	V
TEMPERATURE				
	Specified temperature range		-40 to +85	°C
	Storage temperature range		-60 to +150	°C

 ⁽¹⁾ V_{LED} refers to the voltage drop across the external LED connected between the TXP and TXM pins (in H-bridge mode) and from the TXP and TXM pins to LED_DRV_SUP (in the common anode configuration).
 (2) V_{CABLE} refers to voltage drop across any cable, connector, or any other component in series with the LED.



ELECTRICAL CHARACTERISTICS

Minimum and maximum specifications are at $T_A = -40^{\circ}\text{C}$ to +85°C. Typical specifications are at +25°C. All specifications are at RX_ANA_SUP = RX_DIG_SUP = 3 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and $f_{CLK} = 8$ MHz, unless otherwise noted.

PERFORMANCE (Full-Sign I _{IN_FS} Full-scale input	al Chain)	R_F = 10 kΩ R_F = 25 kΩ	Ę		
I _{IN_FS} Full-scale input					
I _{IN_FS} Full-scale input		R 25 kO		50	μΑ
I _{IN_FS} Full-scale input		1/4 - 50 1/75	2	20	μΑ
I _{IN_FS} Full-scale input	Full-scale input current	$R_F = 50 \text{ k}\Omega$	1	10	μΑ
		$R_F = 100 \text{ k}\Omega$		5	μA
		$R_F = 250 \text{ k}\Omega$		2	μA
		$R_F = 500 \text{ k}\Omega$		1	μA
		$R_F = 1 M\Omega$	0	.5	μA
PRF Pulse repetition	frequency		61	5000	SPS
DC _{PRF} PRF duty cycle				25%	
		$R_F = 10 \text{ k}\Omega$	Ę	50	μA
I _{IN_FS} Full-scale input	current	$R_F = 1 M\Omega$	0	.5	μA
PSRR _{LED} PSRR, transmit	LED driver	With respect to ripple on LED_DRV_SUP	7	75	dB
PSRR _{Tx} PSRR, transmit	control	With respect to ripple on TX_CTRL_SUP	6	60	dB
PSRR _{Rx} PSRR, receiver		With respect to ripple on RX_ANA_SUP and RX_DIG_SUP	6	60	dB
Total integrated	noise current, input-referred	$R_F = 100 \text{ k}\Omega$, PRF = 625 Hz, duty cycle = 5%	3	36	pA _{RMS}
(receiver with tr 0.1-Hz to 5-Hz I	ansmitter loop back, bandwidth)	$R_F = 500 \text{ k}\Omega$, PRF = 625 Hz, duty cycle = 5%	1	13	pA _{RMS}
Noise-free bits ((receiver with transmitter loop	$R_F = 100 \text{ k}\Omega$, PRF = 625 Hz, duty cycle = 5%	14	.3	Bits
N _{FB} back, 0.1-Hz to	5-Hz bandwidth) (1)	$R_F = 500 \text{ k}\Omega$, PRF = 625 Hz, duty cycle = 5%	13	.5	Bits
RECEIVER FUNCTIONAL B	SLOCK LEVEL SPECIFICATION	İ			
Total integrated	noise current, input-referred	$R_F = 500 \text{ k}\Omega$, ambient cancellation enabled, stage 2 gain = 4, PRF = 1300 Hz, LED duty cycle = 25%	1	.4	pA _{RMS}
(receiver alone)	over 0.1-Hz to 5-Hz bandwidth	$R_F = 500 \text{ k}\Omega$, ambient cancellation enabled, stage 2 gain = 4, PRF = 1300 Hz, LED duty cycle = 5%		5	pA _{RMS}
I-V TRANSIMPEDANCE AM	IPLIFIER				
G Gain		$R_F = 10 \text{ k}\Omega$ to $R_F = 1 \text{ M}\Omega$	See the Receiver Ch for detail		V/µA
Gain accuracy			±7'	%	
Feedback resist	tance	R _F	10k, 25k, 50k, 10 500k, and		Ω
Feedback resist	tor tolerance	R _F	±7′	%	
Feedback capa	citance	C _F	5, 10, 25, 50, 100), and 250	pF
Feedback capa	citor tolerance	C _F	±20	%	•
V _{OD(fs)} Full-scale difference	ential output voltage			1	V
. ,	voltage on input pins	Set internally	0	.9	V
External differen	ntial input capacitance	Includes equivalent capacitance of photodiode, cables, EMI filter, and so forth	10	1000	pF
V _{O(shield)} Shield output vo	oltage, V _{CM}	With a 1-kΩ series resistor and a 10-nF decoupling capacitor to ground	0	.9	V

(1) Noise-free bits (N_{FB}) are defined as:

$$N_{FB} = \log 2 \left(\frac{I_{PD}}{6.6 \times I_{NOISE}} \right)$$

Where:

 $I_{\mbox{\scriptsize PD}}$ is the photodiode current, and $I_{\mbox{\scriptsize NOISE}}$ is the input-referred RMS noise current.

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ELECTRICAL CHARACTERISTICS (continued)

Minimum and maximum specifications are at $T_A = -40^{\circ}\text{C}$ to +85°C. Typical specifications are at +25°C. All specifications are at RX_ANA_SUP = RX_DIG_SUP = 3 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and $f_{CLK} = 8$ MHz, unless otherwise noted.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
AMBIE	NT CANCELLATION STAGE					
G	Gain		1, 1.5, 2	2, 3, and 4		V/V
	Current DAC range		0		10	μΑ
	Current DAC step size			1		μΑ
LOW-P	ASS FILTER					
	Low-pass corner frequency	3-dB attenuation	0.5	and 1		kHz
	Pass-band attenuation, 2 Hz to 10 Hz	Duty cycle = 25%		0.004		dB
	Pass-band attendation, 2 Hz to 10 Hz	Duty cycle = 10%		0.041		dB
ANALC	G-TO-DIGITAL CONVERTER	•				
	Resolution				22	Bits
	Sample rate	See the ADC Operation and Averaging Module section	4	× PRF		SPS
	ADC full-scale voltage			±1.2		V
	ADC conversion time	See the ADC Operation and Averaging Module section	50		PRF / 4	μs
	ADC reset time		2			t _{CLK}
RANS	MITTER				"	
	Output current range		0, 50, 75, 100 (see the LEDCN Register		Control	mA
	LED current DAC error			±5%		
	Output current resolution			8		Bits
	Transmitter noise dynamic range,	At 25-mA output current		110		dB
	over 0.1-Hz to 5-Hz bandwidth	At 100-mA output current		110		dB
	Minimum sample time of LED1 and LED2 pulses			50		μs
	LED	LED_ON = 0		1		μA
	LED current DAC leakage current	LED_ON = 1		50		μA
	LED current DAC linearity	Percent of full-scale current		0.5%		
	Output current settling time	From zero current to 150 mA		7		μs
	(with resistive load)	From 150 mA to zero current		7		μs
DIAGN	OSTICS					
	Direction of disconnection state as a state	EN_SLOW_DIAG = 0 Start of diagnostics after the DIAG_EN register bit is set. End of diagnostic indicated by DIAG_END going high.		8		ms
	Duration of diagnostics state machine	EN_SLOW_DIAG = 1 Start of diagnostics after the DIAG_EN register bit is set. End of diagnostic indicated by DIAG_END going high.		16		ms
	Open fault resistance			> 100		kΩ
	Short fault resistance			< 10		kΩ



ELECTRICAL CHARACTERISTICS (continued)

Minimum and maximum specifications are at $T_A = -40^{\circ}\text{C}$ to +85°C. Typical specifications are at +25°C. All specifications are at RX_ANA_SUP = RX_DIG_SUP = 3 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and $f_{CLK} = 8$ MHz, unless otherwise noted.

	PARAMETER	TEST CONDITIONS	MIN TYP MAX	UNIT
INTERNAL	OSCILLATOR			
f _{CLKOUT}	CLKOUT frequency	With an 8-MHz crystal connected to the XIN and XOUT pins	4	MHz
DC _{CLKOUT}	CLKOUT duty cycle		50%	
	Crystal oscillator start-up time	With an 8-MHz crystal connected to the XIN and XOUT pins	200	μs
EXTERNAL	L CLOCK			
	Maximum allowable external clock jitter		50	ps
TIMING				
	Wake-up time from complete power-down		1000	ms
t _{RESET}	Active low RESET pulse duration		1	μs
t _{DIAGEND}	DIAG_END pulse duration at diagnostics completion		4	CLKOUT cycles
t _{ADCRDY}	ADC_RDY pulse duration		1	CLKOUT cycles
DIGITAL S	IGNAL CHARACTERISTICS			
V _{IH}	Logic high input voltage	AFE_PDN, SPI CLK, SPI SIMO, SPI STE, RESET	0.75 × RX_DIG_SUP	V
V _{IL}	Logic low input voltage	AFE_PDN, SPI CLK, SPI SIMO, SPI STE, RESET	0.25 × RX_DIG_SUP	V
I _{IN}	Logic input current	Digital inputs at V _{IH} or V _{IL}	0.1	μA
V _{OH}	Logic high output voltage	DIAG_END, LED_ALM, PD_ALM, SPI SOMI, ADC_RDY, CLKOUT	RX_DIG_SUP - 0.1	٧
V _{OL}	Logic low output voltage	DIAG_END, LED_ALM, PD_ALM, SPI SOMI, ADC_RDY, CLKOUT	0.1	V
SUPPLY C	URRENT			
	D : 1 1	RX_ANA_SUP = 3.0 V, with 8-MHz clock running, Rx stage 2 disabled	0.6	mA
	Receiver analog supply current	RX_ANA_SUP = 3.0 V, with 8-MHz clock running, Rx stage 2 enabled	0.7	mA
	Receiver digital supply current	RX_DIG_SUP = 3.0 V	0.27	mA
LED_DRV _SUP	LED driver supply current	With zero LED current setting	55	μA
TX_CTRL _SUP	Transmitter control supply current		15	μA
	Complete power-down	Receiver current only (RX_ANA_SUP + RX_DIG_SUP)	5	μA
	(using the AFE_PDN pin)	Transmitter current only (LED_DRV_SUP + TX_CTRL_SUP)	2	μA
	Power-down Rx alone	Receiver current only (RX_ANA_SUP + RX_DIG_SUP)	220	μA
	Power-down Tx alone	Transmitter current only (LED_DRV_SUP + TX_CTRL_SUP)	2	μA

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ELECTRICAL CHARACTERISTICS (continued)

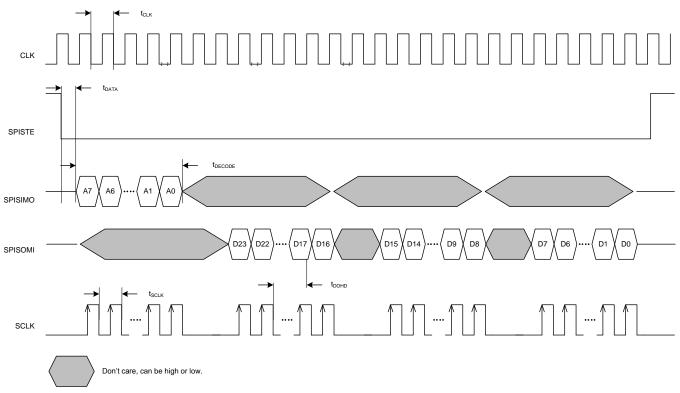
Minimum and maximum specifications are at $T_A = -40^{\circ}\text{C}$ to +85°C. Typical specifications are at +25°C. All specifications are at RX_ANA_SUP = RX_DIG_SUP = 3 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and $f_{CLK} = 8$ MHz, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN TYP	MAX	UNIT	
POWER	DISSIPATION					
_			Normal operation (excluding LEDs)	1.54		mW
$P_{D(q)}$	Quiescent power dissipation	on	Power-down	0.1		μW
	Power-down with the AFE_PDN pin	LED_DRV_SUP	LED_DRV_SUP current value. Does not include LED current.	1		μA
		TX_CTRL_SUP		1		μA
	AFE_PUN PIN	RX_ANA_SUP		5		μΑ
		RX_DIG_SUP		0.1		μA
	Power-down with the PDNAFE register bit	LED_DRV_SUP	LED_DRV_SUP current value. Does not include LED current.	1		μΑ
		TX_CTRL_SUP		1		μA
		RX_ANA_SUP		15		μA
		RX_DIG_SUP		20		μA
	Power-down Rx	LED_DRV_SUP	LED_DRV_SUP current value. Does not include LED current.	50		μΑ
		TX_CTRL_SUP		15		μA
		RX_ANA_SUP		220		μA
		RX_DIG_SUP		220		рА рА рА рА рА рА рА рА рА рА
		LED_DRV_SUP	LED_DRV_SUP current value. Does not include LED current.	2		μА
	Power-down Tx	TX_CTRL_SUP		2		μA
		RX_ANA_SUP		600		μA
		RX_DIG_SUP		230		μA
		LED_DRV_SUP	LED_DRV_SUP current value. Does not include LED current.	50		μA
	After reset, with 8-MHz	TX_CTRL_SUP		15		μA
	clock running	RX_ANA_SUP		600		μA
		RX_DIG_SUP		230		μA
		LED_DRV_SUP	LED_DRV_SUP current value. Does not include LED current.	0.28		μA
	With stage 2 mode enabled and 8-MHz clock	TX_CTRL_SUP		0.1		μA
	running	RX_ANA_SUP		700		μA
		RX_DIG_SUP		0.8		μA



PARAMETRIC MEASUREMENT INFORMATION

SERIAL INTERFACE TIMING



- (1) The SPI_READ register bit must be enabled before attempting a serial readout from the AFE.
- (2) Specify the register address whose contents must be read back on A[7:0].
- (3) The AFE outputs the contents of the specified register on the SOMI pin.

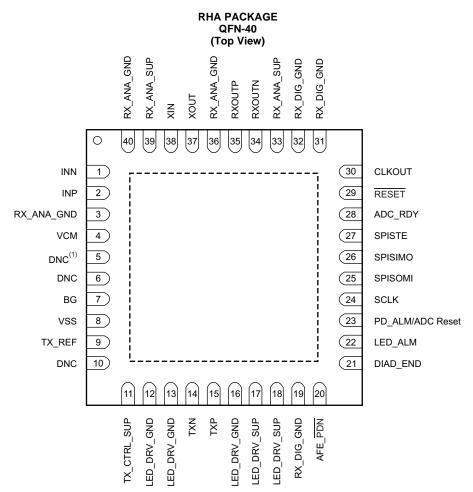
Figure 1. Serial Interface Timing Diagram⁽¹⁾⁽²⁾⁽³⁾

Table 1. Timing Requirements for Figure 1

	PARAMETER	2.0 V ≤ RX	UNIT		
	PARAMETER	MIN	TYP	MAX	UNII
f _{SPICLK}	SPI CLK frequency			8	MHz
t _{SPI_SU}	SPISIMO input data setup time with respect to SCLK rising edge	62.5			ns
t _{SPI_HO}	SPISIMO input data hold time with respect to SCLK rising edge	62.5			ns
t _{SOMI_VAL}	SPISOMI output data setup time	t _{SPICLK} / 4			ns
t _{SOMI_HO}	SPISOMI output data hold time	t _{SPICLK} / 2			ns
t _{RISE}	Rise time from 20% to 80%		5		ns
t _{FALL}	Fall time from 80% to 20%		5		ns



PIN CONFIGURATION



(4) DNC = Do not connect.

PIN DESCRIPTIONS

NAME	NO.	FUNCTION	DESCRIPTION
ADC_RDY	28	Digital	Output signal that indicates ADC conversion completion. Can be connected to the interrupt input pin of an external microcontroller.
AFE_PDN	20	Digital	AFE-only power-down input; active low. Can be connected to the port pin of an external microcontroller.
BG	7	Reference	Decoupling capacitor for internal band-gap voltage to ground. (2.2-μF decoupling capacitor to ground, expected voltage = 1.0 V.)
CLKOUT	30	Digital	Buffered 4-MHz output clock output. Can be connected to the clock input pin of an external microcontroller.
DIAG_END	21	Digital	Output signal that indicates completion of diagnostics. Can be connected to the port pin of an external microcontroller.
DNC ⁽¹⁾	5, 6, 10	_	Do not connect these pins. Leave as open-circuit.
INN	1	Analog	Receiver input pin. Connect to photodiode anode.
INP	2	Analog	Receiver input pin. Connect to photodiode cathode.
LED_DRV_GND	12, 13, 16	Supply	LED driver ground pin, H-bridge. Connect to common board ground.
LED_DRV_SUP	17, 18	Supply	LED driver supply pin, H-bridge. Connect to an external power supply capable of supplying the large LED current, which is drawn by this supply pin.
LED_ALM	22	Digital	Output signal that indicates an LED cable fault. Can be connected to the port pin of an external microcontroller.

(1) Leave pins as open circuit. Do not connect.



PIN DESCRIPTIONS (continued)

NAME	NO.	FUNCTION	DESCRIPTION
PD_ALM/ADC Reset	23	Digital	Output signal that indicates a PD sensor or cable fault. Can be connected to the port pin of an external microcontroller. In ADC bypass mode, the PD_ALM pin can be used to bring out the ADC reset signal.
RESET	29	Digital	AFE-only reset input, active low. Can be connected to the port pin of an external microcontroller.
RX_ANA_GND	3, 36, 40	Supply	Rx analog ground pin. Connect to common board ground.
RX_ANA_SUP	33, 39	Supply	Rx analog supply pin (2.0 V to 3.6 V); 0.1-µF decoupling capacitor to ground
RX_DIG_GND	19, 32	Supply	Rx digital ground pin. Connect to common board ground.
RX_DIG_SUP	31	Supply	Rx digital supply pin (2.0 V to 3.6 V); 0.1-µF decoupling capacitor to ground
RXOUTN	34	Analog	External ADC negative input when in ADC bypass mode
RXOUTP	35	Analog	External ADC positive input when in ADC bypass mode
SCLK	24	SPI	SPI clock pin
SPISIMO	26	SPI	SPI serial in master out
SPISOMI	25	SPI	SPI serial out master in
SPISTE	27	SPI	SPI serial interface enable
TX_CTRL_SUP	11	Supply	Transmit control supply pin, 5 V (0.1-µF decoupling capacitor to ground)
TX_REF	9	Reference	Tx reference voltage
TXN	14	Analog	LED driver out B, H-bridge output. Connect to LED.
TXP	15	Analog	LED driver out B, H-bridge output. Connect to LED.
VCM	4	Reference	Input common-mode voltage output. Connect a series resistor (1 k Ω) and a decoupling capacitor (10 nF) to ground. The voltage across the capacitor can be used to shield (guard) the INP, INM traces. Expected voltage = 0.9 V.
VSS	8	Supply	Substrate ground. Connect to common board ground.
XOUT	37	Digital	Crystal oscillator pins. Connect an external 8-MHz crystal between these pins with the correct load capacitor (as specified by vendor) to ground.
XIN	38	Digital	Crystal oscillator pins. Connect an external 8-MHz crystal between these pins with the correct load capacitor (as specified by vendor) to ground.

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TYPICAL CHARACTERISTICS

At T_A = +25°C, RX_ANA_SUP = RX_DIG_SUP = 3.0 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and f_{CLK} = 8 MHz, unless otherwise noted.

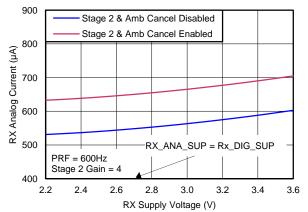


Figure 2. TOTAL Rx CURRENT vs VOLTAGE

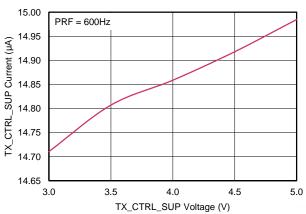


Figure 3. TX_CTRL_SUP CURRENT vs VOLTAGE

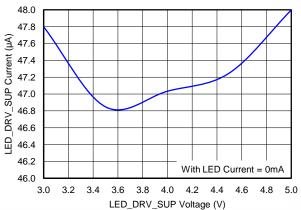


Figure 4. LED_DRV_SUP CURRENT vs VOLTAGE

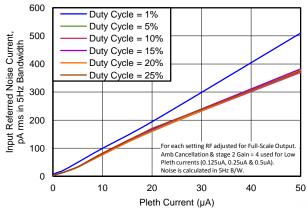


Figure 5. INPUT-REFERRED NOISE CURRENT vs PLETH CURRENT (PRF = 100 Hz) (1)

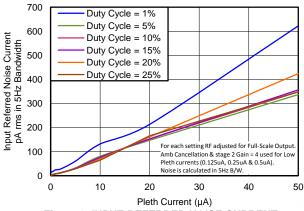


Figure 6. INPUT-REFERRED NOISE CURRENT vs PLETH CURRENT (PRF = 300 Hz)

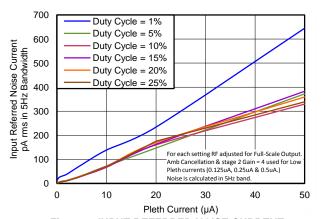


Figure 7. INPUT-REFERRED NOISE CURRENT vs PLETH CURRENT (PRF = 600 Hz)



TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, RX_ANA_SUP = RX_DIG_SUP = 3.0 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and f_{CLK} = 8 MHz, unless otherwise noted.

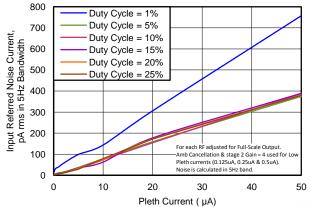


Figure 8. INPUT-REFERRED NOISE CURRENT vs PLETH CURRENT (PRF = 1200 Hz)

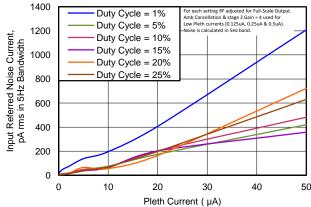
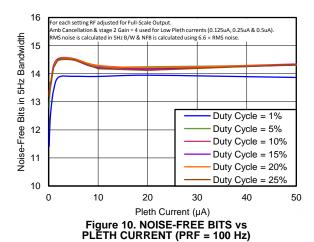


Figure 9. INPUT-REFERRED NOISE CURRENT vs PLETH CURRENT (PRF = 2500 Hz)



16 F.

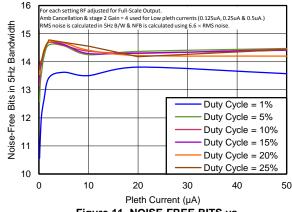
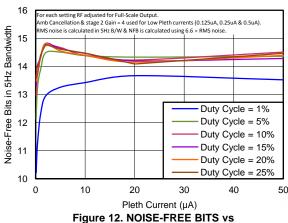


Figure 11. NOISE-FREE BITS vs PLETH CURRENT (PRF = 300 Hz)

or each setting RF adjusted for Full-Scale Output.



PLETH CURRENT (PRF = 600 Hz) (2)

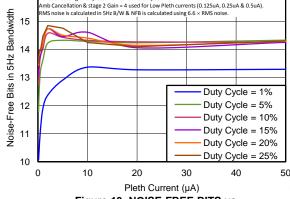


Figure 13. NOISE-FREE BITS vs PLETH CURRENT (PRF = 1200 Hz)

(2) Data at PRF = 625 Hz, 5% duty cycle.

16



TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, RX_ANA_SUP = RX_DIG_SUP = 3.0 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and f_{CLK} = 8 MHz, unless otherwise noted.

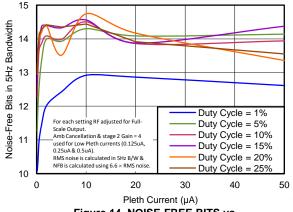


Figure 14. NOISE-FREE BITS vs PLETH CURRENT (PRF = 2500 Hz)

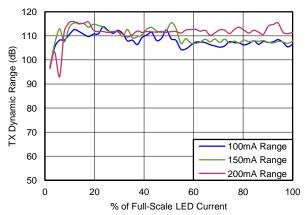


Figure 15. Tx DYNAMIC RANGE

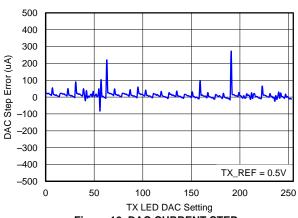


Figure 16. DAC CURRENT STEP vs Tx LED SETTING (Tx Range = 200 mA)

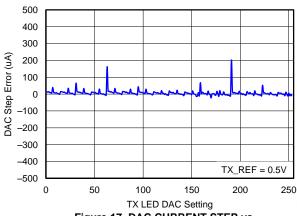


Figure 17. DAC CURRENT STEP vs Tx LED SETTING (Tx Range = 150 mA)

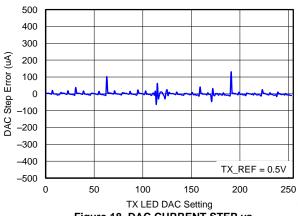


Figure 18. DAC CURRENT STEP vs Tx LED SETTING (Tx Range = 100 mA)

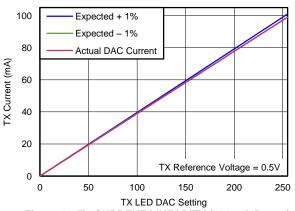


Figure 19. Tx CURRENT LINEARITY (100-mA Range)



TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, RX_ANA_SUP = RX_DIG_SUP = 3.0 V, TX_CTRL_SUP = LED_DRV_SUP = 5 V, and f_{CLK} = 8 MHz, unless otherwise noted.

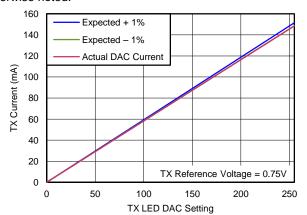
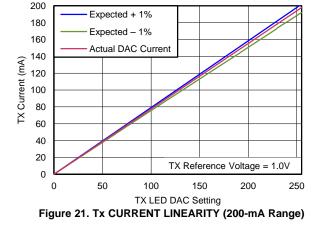


Figure 20. Tx CURRENT LINEARITY (150-mA Range)



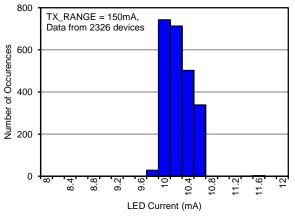


Figure 22. LED CURRENT WITH Tx DAC SETTING = 17 (10 mA)

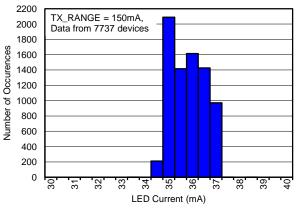


Figure 23. LED CURRENT WITH Tx DAC SETTING = 60 (35 mA)

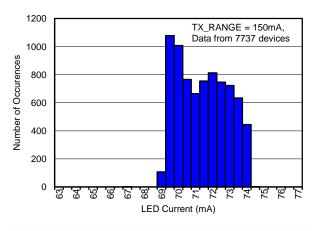


Figure 24. LED CURRENT WITH Tx DAC SETTING = 120 (70 mA)

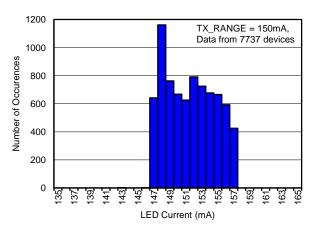


Figure 25. LED CURRENT WITH Tx DAC SETTING = 255 (150 mA)



OVERVIEW

The AFE4490 is a complete analog front-end (AFE) solution targeted for pulse-oximeter applications. The device consists of a low-noise receiver channel, an LED transmit section, and diagnostics for sensor and LED fault detection. To ease clocking requirements and provide the low-jitter clock to the AFE, an oscillator is also integrated that functions from an external crystal. The device communicates to an external microcontroller or host processor using an SPI interface. Figure 26 shows a detailed block diagram for the AFE4490. The blocks are described in more detail in the following sections.

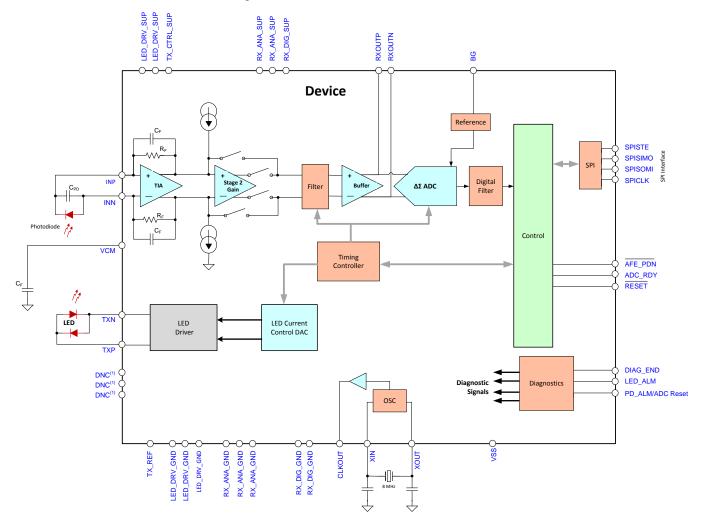


Figure 26. Detailed Block Diagram

Product Folder Links: AFE4490



RECEIVER CHANNEL

This section describes the receiver channel functionality.

Receiver Front-End

The receiver consists of a differential current-to-voltage (I-V) transimpedance amplifier that converts the input photodiode current into an appropriate voltage, as shown in Figure 27. The feedback resistor of the amplifier (R_F) is programmable to support a wide range of photodiode currents. Available R_F values include: 1 M Ω , 500 k Ω , 250 k Ω , 100 k Ω , 50 k Ω , 25 k Ω , and 10 k Ω .

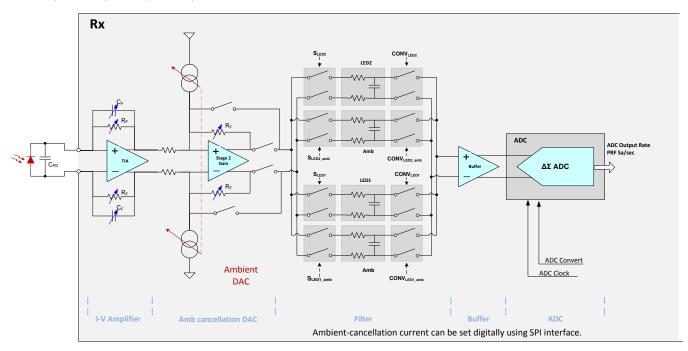


Figure 27. Receiver Front-End

The R_F amplifier and the feedback capacitor (C_F) form a low-pass filter for the input signal current. Always ensure that the low-pass filter has sufficiently high bandwidth (as shown by Equation 1) because the input current consists of pulses. For this reason, the feedback capacitor is also programmable. Available C_F values include: 5 pF, 10 pF, 25 pF, 50 pF, 100 pF, and 250 pF. Any combination of these capacitors can also be used.

$$R_F \times C_F \le \frac{Rx \text{ Sample Time}}{10}$$
 (1)

The output voltage of the I-V amplifier includes the pleth component (the desired signal) and a component resulting from the ambient light leakage. The I-V amplifier is followed by the second stage, which consists of a current digital-to-analog converter (DAC) that sources the cancellation current and an amplifier that gains up the pleth component alone. The amplifier has five programmable gain settings: 1, 1.5, 2, 3, and 4. The gained-up pleth signal is then low-pass filtered (500-Hz bandwidth) and buffered before driving a 22-bit ADC. The current DAC has a cancellation current range of 10 μ A with 10 steps (1 μ A each). The DAC value can be digitally specified with the SPI interface.

The output of the ambient cancellation amplifier is separated into LED2 and LED1 channels. When LED2 is on, the amplifier output is filtered and sampled on capacitor C_R . Similarly, the LED1 signal is sampled on the C_{LED1} capacitor when LED1 is ON. In between the LED2 and LED1 pulses, the idle amplifier output is sampled to estimate the ambient signal on capacitors C_{LED2} amb and C_{LED1} amb.

The sampling duration is termed the Rx sample time and is programmable for each signal, independently. Sampling can start after the I-V amplifier output is stable (to account for LED and cable settling times). The Rx sample time is used for all dynamic range calculations; the minimum time supported is 50 μ s.



A single, 22-bit ADC converts the sampled LED2, LED1, and ambient signals sequentially. Each conversion takes a maximum of 25% of the pulse repetition period (PRP) and provides a single digital code at the ADC output. As discussed in the *Receiver Timing* section, the conversions are staggered so that the LED2 conversion starts after the end of the LED2 sample phase, and so on. This configuration also means that the Rx sample time for each signal is no greater than 25% of the pulse repetition period.

Note that four data streams are available at the ADC output (LED2, LED1, ambient LED2, and ambient LED1) at the same rate as the pulse repetition frequency. The ADC is followed by a digital ambient subtraction block that additionally outputs the (LED2 – ambient LED2) and (LED1 – ambient LED1) data values.

Ambient Cancellation Scheme

The receiver provides digital samples corresponding to ambient duration. The host processor (external to the AFE) can use these ambient values to estimate the amount of ambient light leakage. The processor must then set the value of the ambient cancellation DAC using the SPI, as shown in Figure 28.

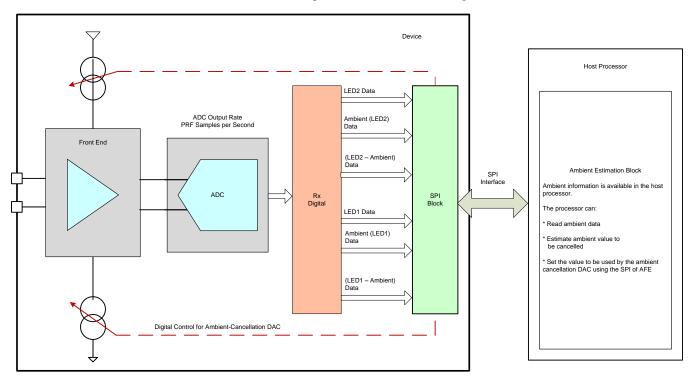


Figure 28. Ambient Cancellation Loop (Closed by the Host Processor)



Using the set value, the ambient cancellation stage subtracts the ambient component and gains up only the pleth component of the received signal, as shown in Figure 29.

The amplifier gain is programmable to 1, 1.5, 2, 3, and 4.

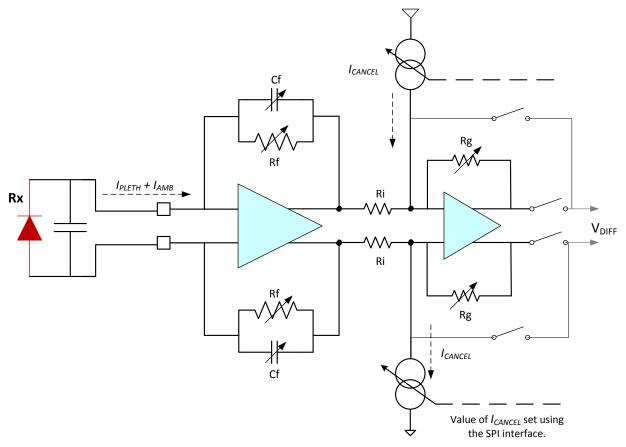


Figure 29. Front-End (I-V Amplifier and Cancellation Stage)

The differential output of the second stage is V_{DIFF}, as given by Equation 2:

$$V_{\text{DIFF}} = 2 \times \left[I_{\text{PLETH}} \times \frac{R_{\text{F}}}{R_{\text{I}}} + I_{\text{AMB}} \times \frac{R_{\text{F}}}{R_{\text{I}}} - I_{\text{CANCEL}} \right] \times R_{\text{G}}$$

Where:

 $R_1 = 100 \text{ k}\Omega$

I_{PLETH} = photodiode current pleth component,

I_{AMB} = photodiode current ambient component, and

 I_{CANCEL} = the cancellation current DAC value (as estimated by the host processor). (2)

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Receiver Control Signals

LED2 sample phase (S_{LED2}): When this signal is high, the amplifier output corresponds to the LED2 on-time. The amplifier output is filtered and sampled into capacitor C_{LED2} . To avoid settling effects resulting from the LED or cable, program S_{LED2} to start after the LED turns on. This settling delay is programmable.

Ambient sample phase (S_{LED2_amb}): When this signal is high, the amplifier output corresponds to the LED2 off-time and can be used to estimate the ambient signal (for the LED2 phase). The amplifier output is filtered and sampled into capacitor C_{LED2_amb} .

LED1 sample phase (S_{LED1}): When this signal is high, the amplifier output corresponds to the LED1 on-time. The amplifier output is filtered and sampled into capacitor C_{LED1} . To avoid settling effects resulting from the LED or cable, program S_{LED1} to start after the LED turns on. This settling delay is programmable.

Ambient sample phase (S_{LED1_amb}): When this signal is high, the amplifier output corresponds to the LED1 off-time and can be used to estimate the ambient signal (for the LED1 phase). The amplifier output is filtered and sampled into capacitor C_{LED1_amb} .

LED2 convert phase (CONV_{LED2}): When this signal is high, the voltage sampled on C_{LED2} is buffered and applied to the ADC for conversion. The conversion time duration is always 25% of the pulse repetition period. At the end of the conversion, the ADC provides a single digital code corresponding to the LED2 sample.

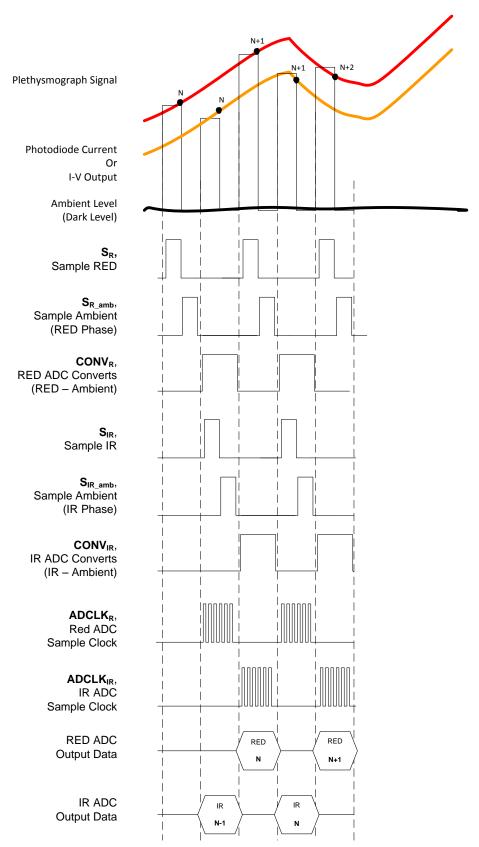
Ambient convert phases (CONV_{LED2_amb}, **CONV**_{LED1_amb}): When this signal is high, the voltage sampled on C_{LED2_amb} (or C_{LED1_amb}) is buffered and applied to the ADC for conversion. The conversion time duration is always 25% of the pulse repetition period. At the end of the conversion, the ADC provides a single digital code corresponding to the ambient sample.

LED1 convert phase (CONV_{LED1}): When this signal is high, the voltage sampled on C_{LED1} is buffered and applied to the ADC for conversion. The conversion time duration is always 25% of the pulse repetition period. At the end of the conversion, the ADC provides a single digital code corresponding to the LED1 sample.

Receiver Timing

See Figure 30 for a timing diagram detailing the control signals related to the LED on-time, Rx sample time, and the ADC conversion times for each channel.





NOTE: Relationship to the AFE4490EVM is: LED1 = IR and LED2 = RED.

Figure 30. Rx Timing Diagram



CLOCKING AND TIMING SIGNAL GENERATION

The crystal oscillator generates a master clock signal using an external 8-MHz crystal. A divide-by-2 block converts the 8-MHz clock to 4 MHz, which is used by the AFE to operate the timer modules, ADC, and diagnostics. The 4-MHz clock is buffered and output from the AFE in order to clock an external microcontroller. The clocking functionality is shown in Figure 31.

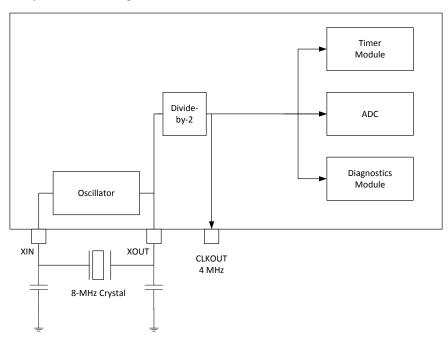


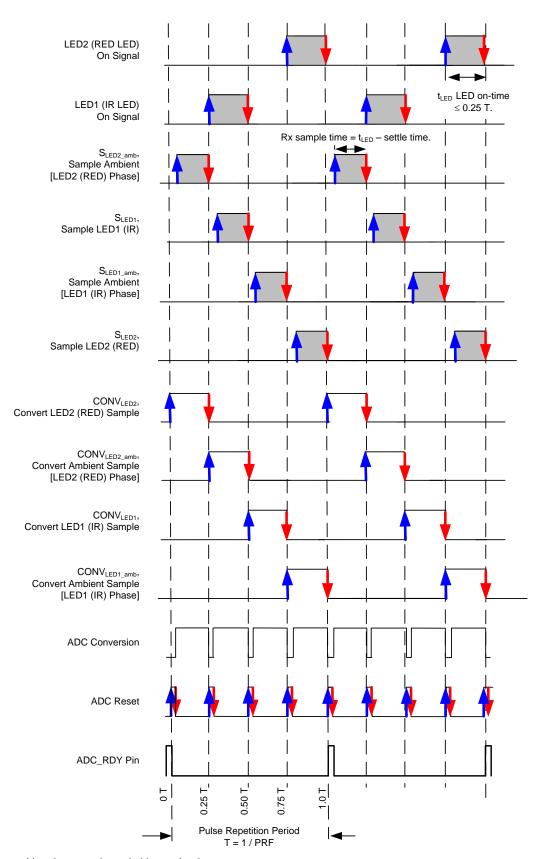
Figure 31. AFE Clocking

TIMER MODULE

See Figure 32 for a timing diagram detailing the various timing edges that are programmable using the timer module. The rising and falling edge positions of 11 signals can be controlled. The module uses a single 16-bit counter (running off of the 4-MHz clock) to set the time-base.

All timing signals are set with reference to the pulse repetition period (PRP). Therefore, a dedicated compare register compares the 16-bit counter value with the reference value specified in the PRF register. Every time that the 16-bit counter value is equal to the reference value in the PRF register, the counter is reset to '0'.





NOTE: Programmable edges are shown in blue and red.

Figure 32. AFE Control Signals



For the 11 signals in Figure 30, the start and stop edge positions are programmable with respect to the PRF period. Each signal uses a separate timer compare module that compares the counter value with preprogrammed reference values for the start and stop edges. All reference values can be set using the SPI interface.

When the counter value equals the start reference value, the output signal is set. When the counter value equals the stop reference value, the output signal is reset. Figure 33 shows a diagram of the timer compare register. With a 4-MHz clock, the edge placement resolution is 0.25 µs. The ADC conversion signal requires four pulses in each PRF clock period. The 11th timer compare register uses four sets of start and stop registers to control the ADC conversion signal.

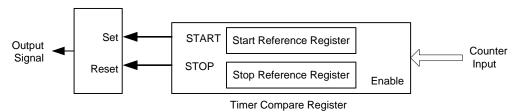


Figure 33. Compare Register

The ADC conversion signal requires four pulses in each PRF clock period. Timer compare register 11 uses four sets of start and stop registers to control the ADC conversion signal, as shown in Figure 34.

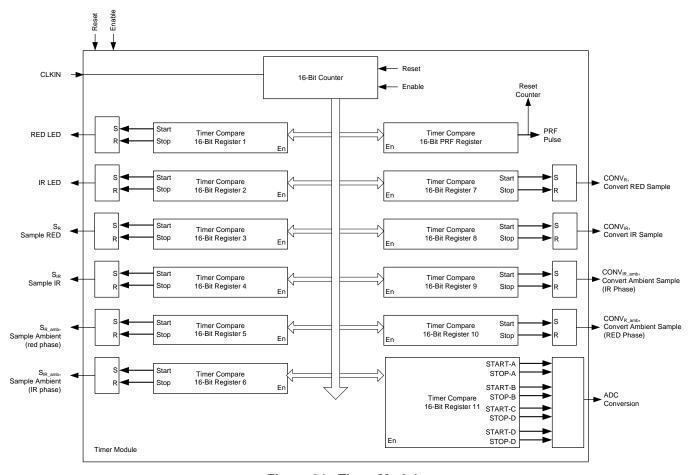


Figure 34. Timer Module



Using the Timer Module

The timer module registers can be used to program the start and end instants in units of 4-MHz clock cycles. These timing instants and the corresponding registers are listed in Table 2.

Note that the device does not restrict the values in these registers; thus, the start and end edges can be positioned anywhere within the pulse repetition period. Care must be taken by the user to program suitable values in these registers to avoid overlapping the signals and to make sure none of the edges exceed the value programmed in the PRP register. Writing the same value in the start and end registers results in a pulse duration of one clock cycle. The following steps describe the timer sequencing configuration:

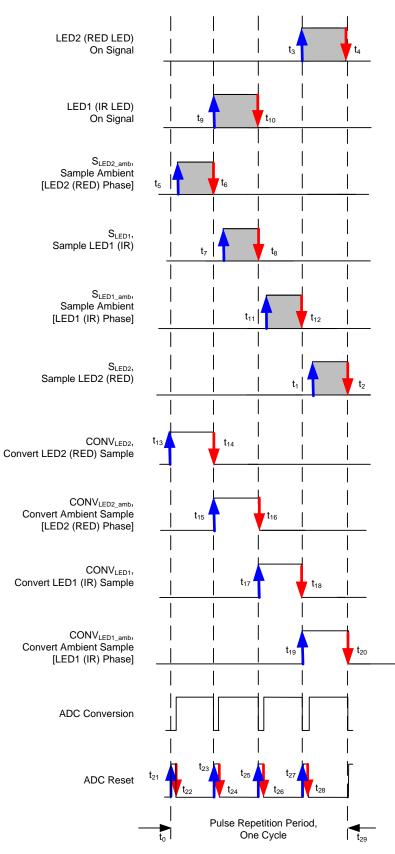
- 1. With respect to the start of the PRP period (indicated by timing instant t_0 in Figure 35), the sequence of conversions must be followed in order: convert LED2 \rightarrow LED2 ambient \rightarrow LED1 \rightarrow LED1 ambient.
- 2. Also, starting from t₀, the sequence of sampling instants must be staggered with respect to the respective conversions as follows: sample LED2 ambient → LED1 → LED1 ambient → LED2.
- 3. Finally, align the edges for the two LED pulses with the respective sampling instants.

Table 2. Clock Edge Mapping to SPI Registers

TIME INSTANT (See Figure 35 and Figure 36)	DESCRIPTION	CORRESPONDING REGISTER ADDRESS AND REGISTER BITS	EXAMPLE (Decimal)
t ₀	Start of pulse repetition period	No register control	_
t ₁	Start of sample LED2 pulse	Sample LED2 start count (bits 15-0 of register 01h)	4800
t ₂	End of sample LED2 pulse	Sample LED2 end count (bits 15-0 of register 02h)	6399
t ₃	Start of LED2 pulse	LED2 start count (bits 15-0 of register 03h)	4800
t ₄	End of LED2 pulse	LED2 end count (bits 15-0 of register 04h)	6399
t ₅	Start of sample LED2 ambient pulse	Sample ambient LED2 start count (bits 15-0 of register 05h)	0
t ₆	End of sample LED2 ambient pulse	Sample ambient LED2 end count (bits 15-0 of register 06h)	1599
t ₇	Start of sample LED1 pulse	Sample LED1 start count (bits 15-0 of register 07h)	1600
t ₈	End of sample LED1 pulse	Sample LED1 end count (bits 15-0 of register 08h)	3199
t ₉	Start of LED1 pulse	LED1 start count (bits 15-0 of register 09h)	1600
t ₁₀	End of LED1 pulse	LED1 end count (bits 15-0 of register 0Ah)	3199
t ₁₁	Start of sample LED1 ambient pulse	Sample ambient LED1 start count (bits 15-0 of register 0Bh)	3200
t ₁₂	End of sample LED1 ambient pulse	Sample ambient LED1 end count (bits 15-0 of register 0Ch)	4700
t ₁₃	Start of convert LED2 pulse	LED2 convert start count (bits 15-0 of register 0Dh)	0
t ₁₄	End of convert LED2 pulse	LED2 convert end count (bits 15-0 of register 0Eh)	1599
t ₁₅	Start of convert LED2 ambient pulse	LED2 ambient convert start count (bits 15-0 of register 0Fh)	1600
t ₁₆	End of convert LED2 ambient pulse	LED2 ambient convert end count (bits 15-0 of register 10h)	3199
t ₁₇	Start of convert LED1 pulse	LED1 convert start count (bits 15-0 of register 11h)	3200
t ₁₈	End of convert LED1 pulse	LED1 convert end count (bits 15-0 of register 12h)	4799
t ₁₉	Start of convert LED1 ambient pulse	LED1 ambient convert start count (bits 15-0 of register 13h)	4800
t ₂₀	End of convert LED1 ambient pulse	LED1 ambient convert end count (bits 15-0 of register 14h)	6399
t ₂₁	Start of first ADC conversion reset pulse	ADC reset 0 start count (bits 15-0 of register 15h)	0
t ₂₂	End of first ADC conversion reset pulse	ADC reset 0 end count (bits 15-0 of register 16h)	0
t ₂₃	Start of second ADC conversion reset pulse	ADC reset 1 start count (bits 15-0 of register 17h)	1600
t ₂₄	End of second ADC conversion reset pulse	ADC reset 0 end count (bits 15-0 of register 18h)	1600
t ₂₅	Start of third ADC conversion reset pulse	ADC reset 2 start count (bits 15-0 of register 19h)	3200
t ₂₆	End of third ADC conversion reset pulse	ADC reset 0 end count (bits 15-0 of register 1Ah)	3200
t ₂₇	Start of fourth ADC conversion reset pulse	ADC reset 3 start count (bits 15-0 of register 1Bh)	4800
t ₂₈	End of fourth ADC conversion reset pulse	ADC reset 0 end count (bits 15-0 of register 1Ch)	4800
t ₂₉	End of pulse repetition period	Pulse repetition period count (bits 15-0 of register 1Dh)	6399

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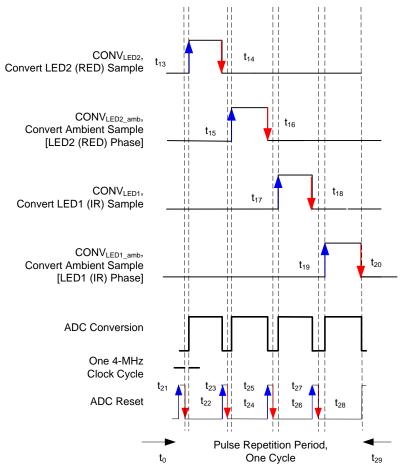




(1) RED = LED2, IR = LED1.

Figure 35. Programmable Clock Edges





(1) RED = LED2, IR = LED1.

Figure 36. Relationship Between the ADC Reset and ADC Conversion Signals

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ADC OPERATION AND AVERAGING MODULE

The ADC reset signal must be positioned at 25% intervals of the pulse repetition period (that is, 0%, 25%, 50%, and 75%). After the falling edge of the ADC reset signal, the ADC conversion phase starts. Each ADC conversion takes $50 \mu s$.

There are two modes of operation: without averaging and with averaging. The averaging mode can average multiple ADC samples and reduce noise to improve dynamic range because the ADC conversion time is usually shorter than 25% of the pulse repetition period. Figure 37 shows a diagram of the averaging module.

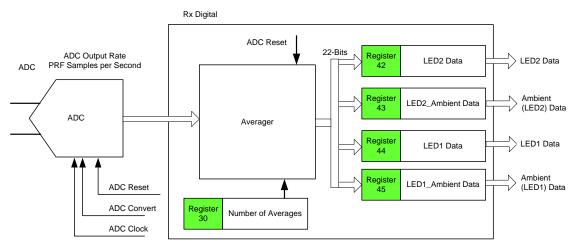


Figure 37. Averaging Module

Operation Without Averaging

In this mode, the ADC outputs a digital sample one time for every 50 µs. At the next rising edge of the ADC reset signal, the first 22-bit conversion value is written into the result registers sequentially as follows (see Figure 38):

- At the 25% reset signal, the first 22-bit ADC sample is written to register 2Ah.
- At the 50% reset signal, the first 22-bit ADC sample is written to register 2Bh.
- At the 75% reset signal, the first 22-bit ADC sample is written to register 2Ch.
- At the next 0% reset signal, the first 22-bit ADC sample is written to register 2Dh. The contents of registers 2Ah and 2Bh are written to register 2Eh and the contents of registers 2Ch and 2Dh are written to register 2Fh.

At the rising edge of the ADC_RDY signal, the contents of all six result registers can be read out.

Operation With Averaging

In this mode, all ADC digital samples are accumulated and averaged after every 50 µs. At the next rising edge of the ADC reset signal, the average value (22-bit) is written into the output registers sequentially as follows (see Figure 39):

- At the 25% reset signal, the averaged 22-bit word is written to register 2Ah.
- At the 50% reset signal, the averaged 22-bit word is written to register 2Bh.
- At the 75% reset signal, the averaged 22-bit word is written to register 2Ch.
- At the next 0% reset signal, the averaged 22-bit word is written to register 2Dh. The contents of registers 2Ah and 2Bh are written to register 2Eh and the contents of registers 2Ch and 2Dh are written to register 2Fh.

At the rising edge of the ADC_RDY signal, the contents of all six result registers can be read out.



The number of samples to be used per conversion phase is specified in the CONTROL1 register (NUMAV[7:0]). The user must specify the correct value for the number of averages, as described in Equation 3:

$$NUMAV[7:0] + 1 = \frac{0.25 \times Pulse Repetition Period}{50 \ \mu s}$$
(3)

When the number of averages is '0', the averaging is disabled and only one ADC sample is written to the result registers.

Note that he number of average conversions is limited by 25% of the PRF. For example, eight samples can be averaged with PRF = 625 Hz, and four samples can be averaged with PRF = 1250 Hz.

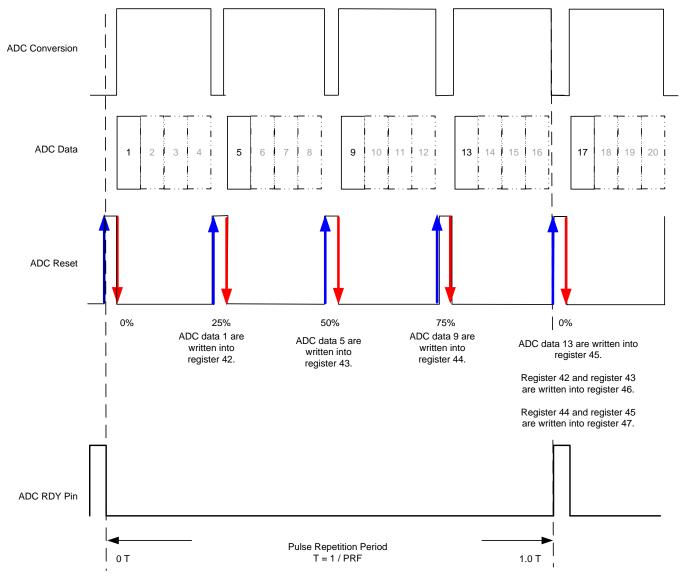
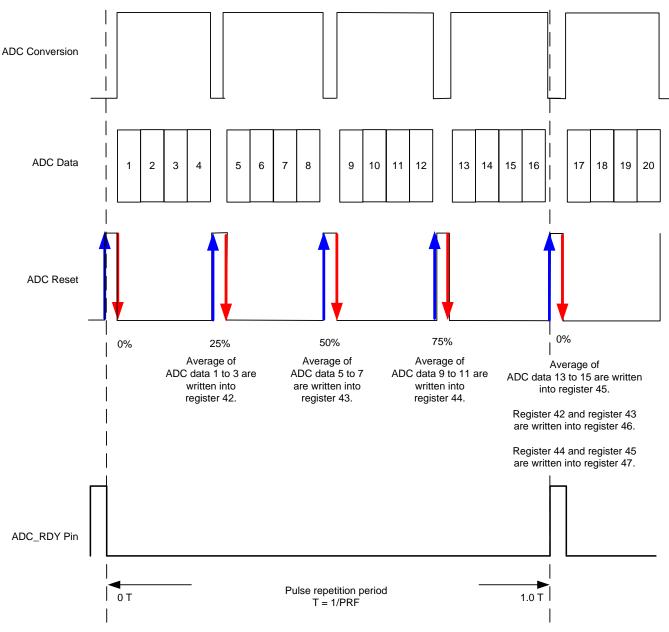


Figure 38. ADC Data Without Averaging (When Number of Averages = 0)





NOTE: Example is with three averages. The value of the NUMAVG[7:0] register bits = 2.

Figure 39. ADC Data with Averaging Enabled



AFE ANALOG OUTPUT MODE (ADC Bypass Mode)

The ADC bypass mode brings out the analog output voltage of the receiver front-end on two pins (RXOUTP, RXOUTN), around a common-mode voltage of approximately 0.9 V. In this mode, the internal ADC of the AFE4490 is disabled. Figure 40 shows a block diagram of this mode.

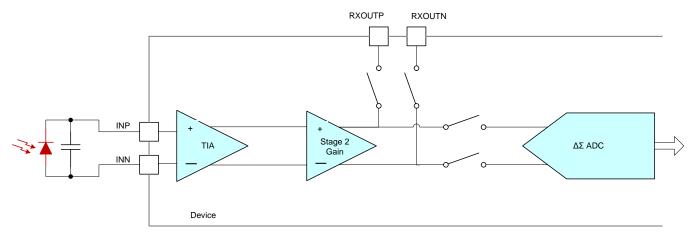


Figure 40. AFE4490 Set to ADC Bypass Mode

In ADC bypass mode, one of the internal clocks (ADC_Reset) can be brought out on the PD_ALM pin, as shown in Figure 41. This signal can be used to convert each of the four phases (within every pulse repetition period). Additionally, the ADC_RDY signal can be used to synchronize the external ADC with the AFE. See Figure 42 for the timing of this mode.

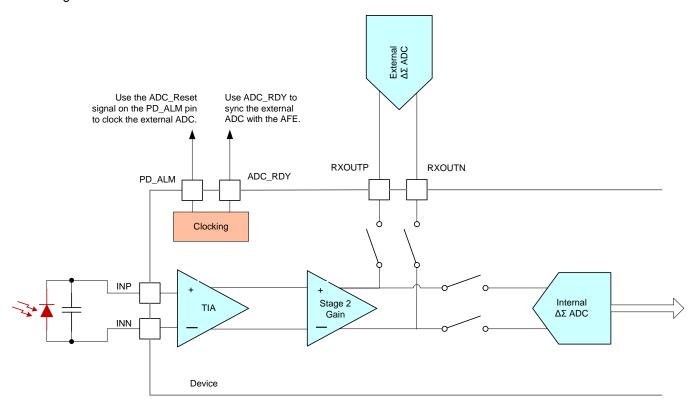
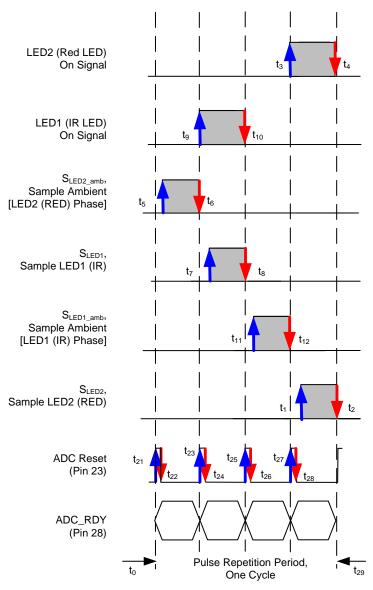


Figure 41. AFE4490 in ADC Bypass Mode with ADC_Reset to PD_ALM Pin





NOTE: RED = LED2, IR = LED1.

Figure 42. AFE4490 Analog Output Mode (ADC Bypass) Timing Diagram

In ADC bypass mode, the ADC reset signal can be used to start conversions with the external ADC. Use registers 15h through 1Ch to position the ADC reset signal edges appropriately. Also, use the EN_RSTCLK on the PD_ALM pin register bit to bring out the ADC reset signal to the PD_ALM pin. ADC_RDY can be used to indicate the start of the pulse repetition period to the external ADC.



RECEIVER SUBSYSTEM POWER PATH

The block diagram in Figure 43 shows the AFE4490 Rx subsystem power routing.

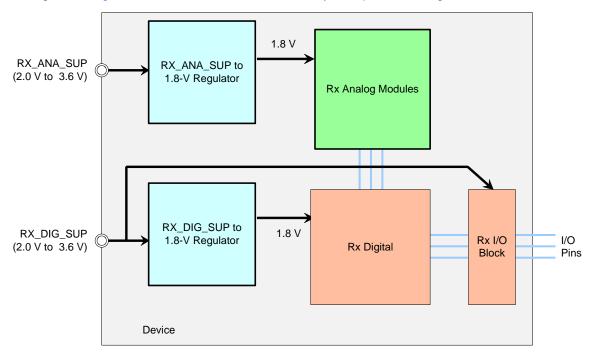


Figure 43. Receive Subsystem Power Routing



TRANSMIT SECTION

The transmit section integrates the LED driver and the LED current control section with 8-bit resolution. This integration is designed to meet the specified dynamic range (based on a 1-sigma LED current noise).

The LED2 and LED1 reference currents can be independently set. The current source (I_{LED}) locally regulates and ensures that the actual LED current tracks the specified reference.

Two LED driver schemes are supported:

- An H-bridge drive for a two-terminal back-to-back LED package, as shown in Figure 44. The minimum H-bridge supply voltage must be 2.5 V + (maximum voltage drop across the LED).
- A push-pull drive for a three-terminal LED package; see Figure 45. The minimum external supply voltage = 2.0 V + (maximum voltage drop across the LED). This value is the nominal value and depends on the registry LED current settings (refer to the LED_RANGE[1:0] bits in the LEDCNTRL register).

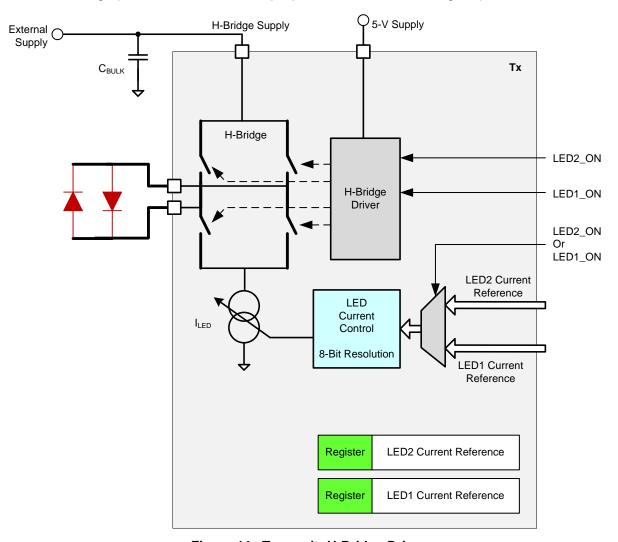


Figure 44. Transmit: H-Bridge Drive



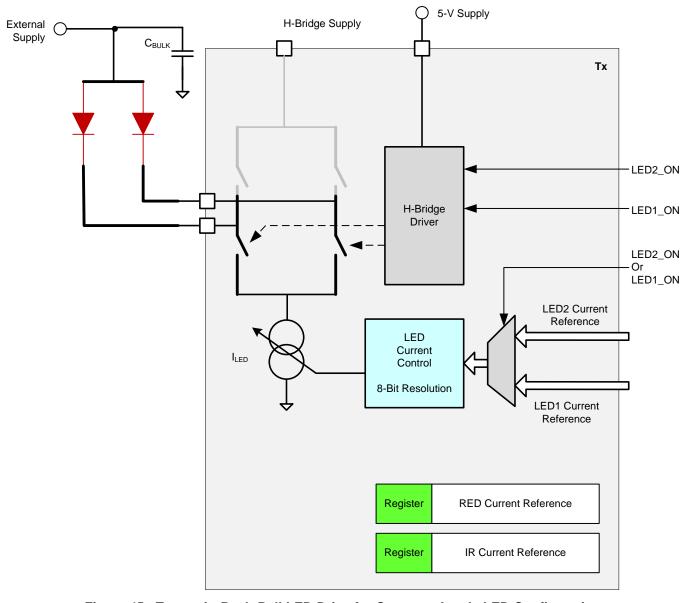


Figure 45. Transmit: Push-Pull LED Drive for Common Anode LED Configuration



Transmitter Power Path

The block diagram in Figure 46 shows the AFE4490 Tx subsystem power routing.

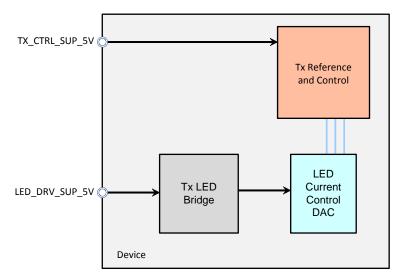


Figure 46. Transmit Subsystem Power Routing

LED Power Reduction During Periods of Inactivity

The diagram in Figure 47 shows how LED bias current passes 50 µA whenever LED_ON occurs. In order to minimize power consumption in periods of inactivity, the LED_ON control must be turned off.

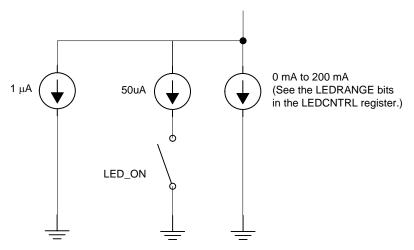


Figure 47. LED Bias Current

Product Folder Links: AFE4490

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DIAGNOSTICS

The device includes diagnostics to detect open or short conditions of the LED and photosensor, LED current profile feedback, and cable on or off detection.

Photodiode-Side Fault Detection

Figure 48 shows the diagnostic for the photodiode-side fault detection.

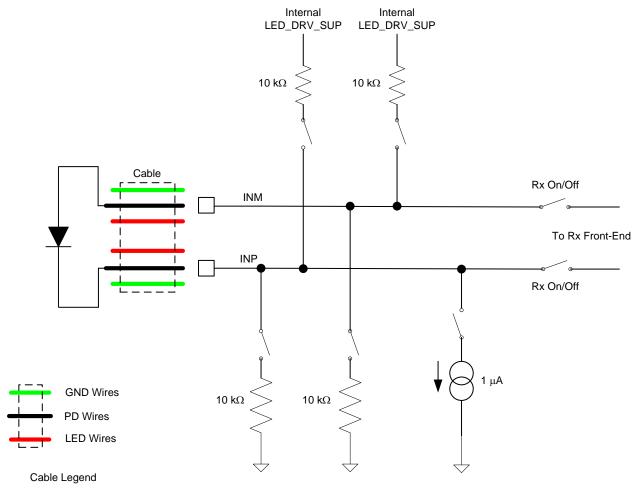


Figure 48. Photodiode Diagnostic

Transmitter-Side Fault Detection

Figure 49 shows the diagnostic for the transmitter-side fault detection.

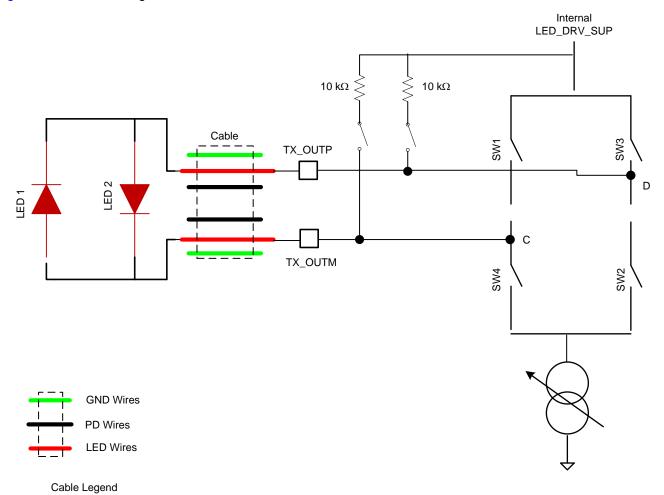


Figure 49. Transmitter Diagnostic



Diagnostics Module

The diagnostics module, when enabled, checks for nine types of faults sequentially. The results of all faults are latched in 11 separate flags. At the end of the sequence, the state of the 11 flags are combined to generate two interrupt signals: PD_ALM for photodiode-related faults and LED_ALM for transmit-related faults. The status of all flags can also be read using the SPI interface. Table 3 details each fault and flag used. Note that the diagnostics module requires all AFE blocks to be enabled in order to function reliably.

Table 3. Fault and Flag Diagnostics⁽¹⁾

MODULE	SEQ.	FAULT	FLAG1	FLAG2	FLAG3	FLAG4	FLAG5	FLAG6	FLAG7	FLAG8	FLAG9	FLAG10	FLAG11
_	_	No fault	0	0	0	0	0	0	0	0	0	0	0
	1	Rx INP cable shorted to LED cable	1										
	2	Rx INM cable shorted to LED cable		1									
PD	3	Rx INP cable shorted to GND cable			1								
	4	Rx INM cable shorted to GND cable				1							
	5	PD open or shorted					1	1					
	6	Tx OUTM line shorted to GND cable							1				
LED	7	Tx OUTP line shorted to GND cable								1			
	8	LED open or shorted									1	1	
	9	LED open or shorted											1

(1) Resistances below 10 $k\Omega$ are considered to be shorted.

Figure 50 shows the timing for the diagnostic function.

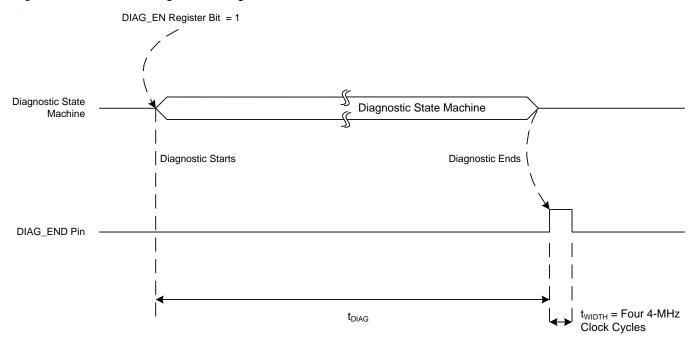


Figure 50. Diagnostic Timing Diagram

By default, the diagnostic function takes $t_{DIAG} = 8$ ms to complete after the DIAG_EN register bit is enabled. By setting the EN_SLOW_DIAG register bit (CONTROL2 register, bit D8) the diagnostic time can be increased to 16 ms.

SERIAL PROGRAMMING INTERFACE

The SPI-compatible serial interface consists of four signals: SCLK (serial clock), SPISOMI (serial interface data output), SPISIMO (serial interface data input), and SPISTE (serial interface enable).

The serial clock (SCLK) is the serial peripheral interface (SPI) serial clock. SCLK shifts in commands and shifts out data from the device. SCLK features a Schmitt-triggered input and clocks data out on SPISOMI. Data are clocked in on the SPISIMO pin. Even though the input has hysteresis, TI recommends keeping SCLK as clean as possible to prevent glitches from accidentally shifting the data. When the serial interface is idle, hold SCLK low.

The SPISOMI (SPI serial out master in) pin is used with SCLK to clock out the AFE4490 data. The SPISIMO (SPI serial in master out) pin is used with SCLK to clock in data to the AFE4490. The SPISTE (SPI serial interface enable) pin enables the serial interface to clock data on the SPISIMO pin in to the device.

READING AND WRITING DATA

The device has a set of internal registers that can be accessed by the serial programming interface formed by the SPISTE, SCLK, SPISIMO, and SPISOMI pins.

Writing Data

When SPISTE is low,

- Serially shifting bits into the device is enabled.
- Serial data (on the SPISIMO pin) are latched at every SCLK rising edge.
- The serial data are loaded into the register at every 32nd SCLK rising edge.

In case the word length exceeds a multiple of 32 bits, the excess bits are ignored. Data can be loaded in multiples of 32-bit words within a single active SPISTE pulse. The first eight bits form the register address and the remaining 24 bits form the register data. Figure 51 shows a diagram of the write timing.

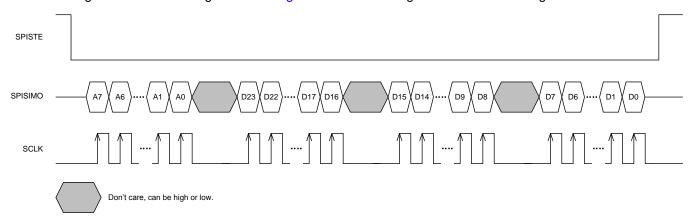
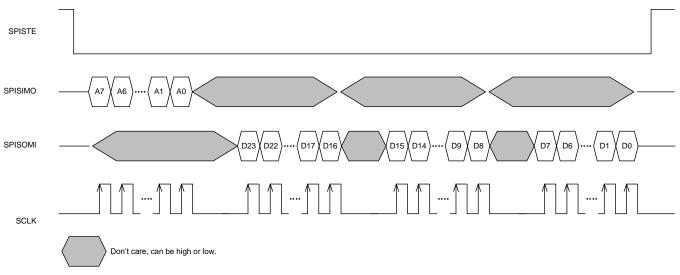


Figure 51. AFE SPI Write Timing Diagram



Reading Data

The AFE4490 includes a mode where the contents of the internal registers can be read back on the SPISOMI pin. This mode may be useful as a diagnostic check to verify the serial interface communication between the external controller and the AFE. To enable this mode, first set the SPI_READ register bit using the SPI write command, as described in the *Writing Data* section. In the next command, specify the SPI register address with the desired content to be read. Within the same SPI command sequence, the AFE outputs the contents of the specified register on the SPISOMI pin. Figure 52 shows a timing diagram for the SPI read operation.



- (1) The SPI_READ register bit must be enabled before attempting a serial readout from the AFE.
- (2) Specify the register address of the content that must be readback on bits A[7:0].
- (3) The AFE outputs the contents of the specified register on the SPISOMI pin.

Figure 52. AFE SPI Read Timing Diagram⁽¹⁾⁽²⁾⁽³⁾

Register Initialization

After power-up, the internal registers must be initialized to the default values. This initialization can be done in one of two ways:

- Through a hardware reset by applying a low-going pulse on the RESET pin, or
- By applying a software reset. Using the serial interface, set SW_RESET (bit D3 in register 00h) high. This setting initializes the internal registers to the default values and then self-resets to '0'. In this case, the RESET pin is kept high (inactive).

AFE SPI Interface Design Considerations

Note that when the AFE4490 is deselected, the SPISOMI, CLKOUT, ADC_RDY, PD_ALM, LED_ALM, and DIAG_END digital output pins do not enter a 3-state mode. This condition, therefore, must be taken into account when connecting multiple devices to the SPI port and for power-management considerations.

AFE REGISTER MAP

The AFE consists of a set of registers that can be used to configure it, such as receiver timings, I-V amplifier settings, transmit LED currents, and so forth. The registers and their contents are listed in Table 4. These registers can be accessed using the AFE SPI interface.

Table 4. AFE Register Map

	ADD	RESS												REGIST	ER DAT	Α										
NAME	Hex	Dec	D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
CONTROLO	00	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	SW_RST	DIAG_EN	TIM_COUNT_RST	SPI_READ
LED2STC	01	1	0	0	0	0	0	0	0	0					•	•		LED2S	TC[15:0]		•		•			
LED2ENDC	02	2	0	0	0	0	0	0	0	0								LED2EN	IDC[15:0]							
LED2LEDSTC	03	3	0	0	0	0	0	0	0	0							I	ED2LED	STC[15:0	0]						
LED2LEDENDC	04	4	0	0	0	0	0	0	0	0							L	ED2LEDI	ENDC[15	:0]						
ALED2STC	05	5	0	0	0	0	0	0	0	0								ALED2S	STC[15:0]							
ALED2ENDC	06	6	0	0	0	0	0	0	0	0								ALED2EI	NDC[15:0)]						
LED1STC	07	7	0	0	0	0	0	0	0	0								LED1S	TC[15:0]							
LED1ENDC	08	8	0	0	0	0	0	0	0	0								LED1EN	IDC[15:0]							
LED1LEDSTC	09	9	0	0	0	0	0	0	0	0							ļ	_ED1LEC	STC[15:0	0]						
LED1LEDENDC	0A	10	0	0	0	0	0	0	0	0							L	ED1LEDI	ENDC[15	:0]						-
ALED1STC	0B	11	0	0	0	0	0	0	0	0								ALED1S	STC[15:0]							
ALED1ENDC	0C	12	0	0	0	0	0	0	0	0								ALED1EI	NDC[15:0)]						
LED2CONVST	0D	13	0	0	0	0	0	0	0	0							l	ED2CON	NVST[15:	0]						
LED2CONVST	0E	14	0	0	0	0	0	0	0	0							L	ED2CON	VEND[15	5:0]						
ALED2CONVST	0F	15	0	0	0	0	0	0	0	0							А	LED2CO	NVST[15	:0]						
ALED2CONVEND	10	16	0	0	0	0	0	0	0	0							AL	.ED2CON	IVEND[1	5:0]						
LED1CONVST	11	17	0	0	0	0	0	0	0	0							L	ED1CO	NVST[15:	0]						
LED1CONVEND	12	18	0	0	0	0	0	0	0	0							L	ED1CON	VEND[15	5:0]						
ALED1CONVST	13	19	0	0	0	0	0	0	0	0							Α	LED1CO	NVST[15	:0]						
ALED1CONVEND	14	20	0	0	0	0	0	0	0	0							AL	ED1CON	VEND[1	5:0]						
ADCRSTCNT0	15	21	0	0	0	0	0	0	0	0								ADCRST	CT0[15:0)]						
ADCRSTENDCT0	16	22	0	0	0	0	0	0	0	0							A	DCREN	DCT0[15:	0]						
ADCRSTSTCT1	17	23	0	0	0	0	0	0	0	0								ADCRST	CT1[15:0)]						
ADCRSTENDCT1	18	24	0	0	0	0	0	0	0	0							A	DCREN	DCT1[15:	0]						
ADCRSTSTCT2	19	25	0	0	0	0	0	0	0	0									CT2[15:0							-
ADCRSTENDCT2	1A	26	0	0	0	0	0	0	0	0							A	DCREN	DCT2[15:	0]						-
ADCRSTSTCT3	1B	27	0	0	0	0	0	0	0	0								ADCRST	CT3[15:0)]						-
ADCRSTENDCT3	1C	28	0	0	0	0	0	0	0	0							A	DCREN	DCT3[15:	0]						
PRPCOUNT	1D	29	0	0	0	0	0	0	0	0								PRPC	T[15:0]							
CONTROL1	1E	30	0	0	0	0	0	0	0	0	0	0	0	0	CLI	KALMPIN	[2:0]	TIMEREN				NUMA	V[7:0]			
SPARE1	1F	31	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Table 4. AFE Register Map (continued)

	ADD	RESS											шар		ER DATA											
NAME	Hex	Dec	D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
TIAGAIN	20	32	0	0	0	0	0	0	0	0	ENSEPGAN	0	0	0	0	0	0	0			F_LED1[4				F_LED1[
TIA_AMB_GAIN	21	33	0	0	0	0		AMBD	AC[3:0]		FLTRCNRSEL	STAGE2EN	0	0	0	ST	G2GAIN[2:0]		CF	F_LED2[4	4:0]		RI	F_LED2[2:0]
LEDCNTRL	22	34	0	0	0	0	0	0	RANG	ED SE[1:0]				LED	1[7:0]							LED	2[7:0]			
CONTROL2	23	35	0	0	0	0	0	TX_REF1	TX_REF0	0	EN_ADC_BYP	0	0	0	TXBRGMOD	0	XTALDIS	EN_SLOW_DIAG	0	0	0	0	0	PDNTX	PDNRX	PDNAFE
SPARE2	24	36	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
SPARE3	25	37	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
SPARE4	26	38	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
RESERVED1	27	39	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
RESERVED2	28	40	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
ALARM	29	41	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	ALMPINCLKEN	0	0	0	0	0	0	0
LED2VAL	2A	42												LED2V	AL[23:0]											
ALED2VAL	2B	43												ALED2\	/AL[23:0]											
LED1VAL	2C	44												LED1V	AL[23:0]											
ALED1VAL	2D	45												ALED1\	/AL[23:0]											
LED2-ALED2VAL	2E	46											LE	D2-ALE	D2VAL[23	3:0]										
LED1-ALED1VAL	2F	47											LE	D1-ALE	01VAL[23	3:0]										
DIAG	30	48	0	0	0	0	0	0	0	0	0	0	0	PD_ALM	LED_ALM	LED10PEN	LEDZOPEN	LEDSC	OUTPSHGND	OUTNSHGND	PDOC	PDSC	INNSCGND	INPSCGND	INNSCLED	INPSCLED

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AFE REGISTER DESCRIPTION

CONTROLO: Control Register 0 (Address = 00h, Reset Value = 0000h)

				_	•		•		•		
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	SW_RST	DIAG_EN	TIM_ COUNT_ RST	SPI_ READ

This register is used for AFE software and count timer reset, diagnostics enable, and SPI read functions.

Bits D[23:4] Must be '0'

Bit D3 SW RST: Software reset

0 = No action (default after reset)

1 = Software reset applied; resets all internal registers to the default values and self-clears

to '0'

Bit D2 DIAG EN: Diagnostic enable

0 = No Action (default after reset)

1 = Diagnostic mode is enabled and the diagnostics sequence starts when this bit is set.

At the end of the sequence, all fault statuses are stored in the DIAG: Diagnostics Flag

Register. Afterwards, the DIAG_EN register bit self-clears to '0'.

Bit D1 TIM_CNT_RST: Timer counter reset

0 = Disables timer counter reset, required for normal timer operation (default after reset)

1 = Timer counters are in reset state

Bit D0 SPI READ: SPI read

0 = SPI read is disabled (default after reset)

1 = SPI read is enabled

LED2STC: Sample LED2 Start Count Register (Address = 01h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED2S	TC[15:0]	
		•	•					•			
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					LED2S	TC[15:0]					

This register sets the start timing value for the LED2 signal sample.

Bits D[23:16] Must be '0'

Bits D[15:0] LED2STC[15:0]: Sample LED2 start count

The contents of this register can be used to position the start of the sample LED2 signal with respect to the pulse repetition period (PRP), as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

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	LED2E	NDC: Saı	mple LEC	2 End C	ount Reg	ister (Ad	dress = 0	2h, Rese	t Value =	0000h)	
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED2EN	IDC[15:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					LED2EN	IDC[15:0]					

This register sets the end timing value for the LED2 signal sample.

Bits D[23:16] Must be '0'

Bits D[15:0] LED2ENDC[15:0]: Sample LED2 end count

The contents of this register can be used to position the end of the sample LED2 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

LED2LEDSTC: LED2 LED Start Count Register (Address = 03h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED2LED	STC[15:0]	
_			_				_			_	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					LED2LED	STC[15:0]					

This register sets the start timing value for when the LED2 signal turns on.

Bits D[23:16] Must be '0'

Bits D[15:0] LED2LEDSTC[15:0]: LED2 start count

The contents of this register can be used to position the start of the LED2 with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

LED2LEDENDC: LED2 LED End Count Register (Address = 04h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED2LEDE	ENDC[15:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					LED2LEDI	ENDC[15:0]					

This register sets the end timing value for when the LED2 signal turns off.

Bits D[23:16] Must be '0'

Bits D[15:0] LED2LEDENDC[15:0]: LED2 end count

The contents of this register can be used to position the end of the LED2 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h

1 = PRP value

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ALED2STC: Sample Ambient LED2 Start Count Register (Address = 05h, Reset Value = 0000h)

						3	•	,			- ,
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		ALED2S	STC[15:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ווט	סוט	Da	Do	וט	סט	טט	D4	DS	DZ	וט	DU
					ALED2S	TC[15:0]					

This register sets the start timing value for the ambient LED2 signal sample.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED2STC[15:0]: Sample ambient LED2 start count

The contents of this register can be used to position the start of the sample ambient LED2 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

ALED2ENDC: Sample Ambient LED2 End Count Register (Address = 06h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		ALED2EN	NDC[15:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					ALED2EI	NDC[15:0]					

This register sets the end timing value for the ambient LED2 signal sample.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED2ENDC[15:0]: Sample ambient LED2 end count

The contents of this register can be used to position the end of the sample ambient LED2 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

LED1STC: Sample LED1 Start Count Register (Address = 07h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED1S	TC[15:0]	
	•										
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					LED1S	TC[15:0]					

Product Folder Links: AFE4490

This register sets the start timing value for the LED1 signal sample.

Bits D[23:17] Must be '0'

Bits D[16:0] LED1STC[15:0]: Sample LED1 start count

The contents of this register can be used to position the start of the sample LED1 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h

1 = PRP value

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LED1ENDC: Sample LED1 End Count (Address = 08h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED1EN	IDC[15:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					LED1EN	IDC[15:0]					

This register sets the end timing value for the LED1 signal sample.

Bits D[23:17] Must be '0'

Bits D[16:0] LED1ENDC[15:0]: Sample LED1 end count

The contents of this register can be used to position the end of the sample LED1 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h1 = PRP value

LED1LEDSTC: LED1 LED Start Count Register (Address = 09h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12		
0	0	0	0	0	0	0	0		LED1LED				
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0		
	LED1LEDSTC[15:0]												

This register sets the start timing value for when the LED1 signal turns on.

Bits D[23:16] Must be '0'

Bits D[15:0] LED1LEDSTC[15:0]: LED1 start count

The contents of this register can be used to position the start of the LED1 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

LED1LEDENDC: LED1 LED End Count Register (Address = 0Ah, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		LED1LEDE		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	LED1LEDENDC[15:0]										

This register sets the end timing value for when the LED1 signal turns off.

Bits D[23:16] Must be '0'

Bits D[15:0] LED1LEDENDC[15:0]: LED1 end count

The contents of this register can be used to position the end of the LED1 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h

1 = PRP value

ALED1STC: Sample Ambient LED1 Start Count Register (Address = 0Bh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ALED1STC[15:0]			
D11	D10	D9	D8	D7	D6	D5	D4	D3 D2 D1 [
	ALED1STC[15:0]											

This register sets the start timing value for the ambient LED1 signal sample.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED1STC[15:0]: Sample ambient LED1 start count

> The contents of this register can be used to position the start of the sample ambient LED1 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the Using the Timer Module section for details.

0 = 0000h1 = PRP value

ALED1ENDC: Sample Ambient LED1 End Count Register (Address = 0Ch, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12		
0	0	0	0	0	0	0	0		ALED1E	NDC[15:0]			
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0		
	ALED1ENDC[15:0]												

This register sets the end timing value for the ambient LED1 signal sample.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED1ENDC[15:0]: Sample ambient LED1 end count

> The contents of this register can be used to position the end of the sample ambient LED1 signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h1 = PRP value

LED2CONVST: LED2 Convert Start Count Register (Address = 0Dh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12		
0	0	0	0	0	0	0	0		LED2CONVST[15:0] D2 D1 D0				
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0		
	LED2CONVST[15:0]												

This register sets the start timing value for the LED2 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] LED2CONVST[15:0]: LED2 convert start count

> The contents of this register can be used to position the start of the LED2 conversion signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h

1 = PRP value



LED2CONVST: LED2 Convert End Count Register (Address = 0Eh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		LED2CON	NVST[15:0]		
D44	44 D40 D0 D0 D7 D6 D5 D4 D2 D2 D4							D4	D0			
D11	D10	D10 D9 D8 D7 D6 D5 D4 D3 D2 D1				D0						
LED2CONVST[15:0]												

This register sets the end timing value for the LED2 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] LED2CONVST[15:0]: LED2 convert end count

> The contents of this register can be used to position the end of the LED2 conversion signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h1 = PRP value

ALED2CONVST: LED2 Ambient Convert Start Count Register (Address = 0Fh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ALED2CO	NVST[15:0]		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	ALED2CONVST[15:0]											

This register sets the start timing value for the ambient LED2 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED2CONVST[15:0]: LED2 ambient convert start count

> The contents of this register can be used to position the start of the LED2 ambient conversion signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the Using the Timer Module section for details.

0 = 0000h1 = PRP value

ALED2CONVEND: LED2 Ambient Convert End Count Register (Address = 10h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		ALED2CON	IVEND[15:0]
						0 0 ALED2CONVEND[15:0]					
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					ALED2CON	VEND[15:0					

This register sets the end timing value for the ambient LED2 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED2CONVEND[15:0]: LED2 ambient convert end count

> The contents of this register can be used to position the end of the LED2 ambient conversion signal with respect to the PRP. The count is specified as the number of 4-MHz clock cycles. Refer to the Using the Timer Module section for details.

0 = 0000h

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1 = PRP value

LED1CONVST: LED1 Convert Start Count Register (Address = 11h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12		
0	0	0	0	0	0	0	0		LED1CONVST[15:0]				
D11	D10	D9	D8	D7	D6	D5	D4	D3					
	LED1CONVST[15:0]												

This register sets the start timing value for the LED1 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] LED1CONVST[15:0]: LED1 convert start count

> The contents of this register can be used to position the start of the LED1 conversion signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h1 = PRP value

LED1CONVEND: LED1 Convert End Count Register (Address = 12h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		LED1CON'	VEND[15:0]		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	LED1CONVEND[15:0]											

This register sets the end timing value for the LED1 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] LED1CONVEND[15:0]: LED1 convert end count

> The contents of this register can be used to position the end of the LED1 conversion signal with respect to the PRP. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h1 = PRP value

ALED1CONVST: LED1 Ambient Convert Start Count Register (Address = 13h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12		
0	0	0	0	0	0	0	0		ALED1CONVST[15:0]				
D11	D10	D9	D8	D7	D6	D5	D4	D3			D0		
	ALED1CONVST[15:0]												

This register sets the start timing value for the ambient LED1 conversion.

Must be '0' Bits D[23:16]

Bits D[15:0] ALED1CONVST[15:0]: LED1 ambient convert start count

> The contents of this register can be used to position the start of the LED1 ambient conversion signal with respect to the PRP, as specified in the PRPCOUNT register. The count is specified as the number of 4-MHz clock cycles. Refer to the Using the Timer Module section for details.

0 = 0000h

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1 = PRP value



ALED1CONVEND: LED1 Ambient Convert End Count Register (Address = 14h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		ALED1CON	VEND[15:0	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
						IVEND[15:0					

This register sets the end timing value for the ambient LED1 conversion.

Bits D[23:16] Must be '0'

Bits D[15:0] ALED1CONVEND[15:0]: LED1 ambient convert end count

The contents of this register can be used to position the end of the LED1 ambient conversion signal with respect to the PRP. The count is specified as the number of 4-MHz clock cycles. Refer to the *Using the Timer Module* section for details.

0 = 0000h 1 = PRP value

ADCRSTCNT0: ADC Reset 0 Start Count Register (Address = 15h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ADCRST	CNT0[15:0]		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D0		
	ADCRSTCNT0[15:0]											

This register sets the start position of the ADC0 reset conversion signal.

Bits D[23:16] Must be '0'

Bits D[15:0] ADCRSTCNT0[15:0]: ADC RESET 0 start count

The contents of this register can be used to position the start of the ADC reset conversion signal (default value after reset is 0000h). Refer to the *Using the Timer Module* section for details.

ADCRSTENDCT0: ADC Reset 0 End Count Register (Address = 16h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ADCRSTEN	NDCT0[15:0]]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	ADCRSTENDCT0[15:0]											

This register sets the end position of the ADC0 reset conversion signal.

Bits D[23:16] Must be '0'

Bits D[15:0] ADCRSTENDCT0[15:0]: ADC RESET 0 end count

The contents of this register can be used to position the end of the ADC reset conversion signal (default value after reset is 0000h). Refer to the *Using the Timer Module* section for details.

SBAS602B - DECEMBER 2012 - REVISED FEBRUARY 2013

ADCRST	STCT1: A	DC Rese	t 1 Start	Count R	egister (A	ddress =	: 17h, Res	set Value	= 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ADCRSTS	TCT1[15:0]		
	D	-										
11ט	D11 D10 D9 D8 D7 D6 D5 D4							D3	D2	D1	D0	
	ADCRSTSTCT1[15:0]											

This register sets the start position of the ADC1 reset conversion signal.

Bits D[23:16] Must be '0'

ADCRSTSTCT1[15:0]: ADC RESET 1 start count Bits D[15:0]

> The contents of this register can be used to position the start of the ADC reset conversion. Refer to the *Using the Timer Module* section for details.

ADCRSTENDCT1: ADC Reset 1 End Count Register (Address = 18h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		ADCRSTEN	NDCT1[15:0]]
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
					ADCRSTE	NDCT1[15:0]				

This register sets the end position of the ADC1 reset conversion signal.

Bits D[23:16] Must be '0'

Bits D[15:0] ADCRSTENDCT1[15:0]: ADC RESET 1 end count

> The contents of this register can be used to position the end of the ADC reset conversion. Refer to the *Using the Timer Module* section for details.

ADCRSTSTCT2: ADC Reset 2 Start Count Register (Address = 19h, Reset Value = 0000h)

0 0 0 0 0 0 0 ADCRSTSTCT2[15:0]		D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
		0	0	0	0	0	0	0	0		ADCRSTS	TCT2[15:0]	
D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0		D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ADCRSTSTCT2[15:0]													

This register sets the start position of the ADC2 reset conversion signal.

Bits D[23:16] Must be '0'

ADCRSTSTCT2[15:0]: ADC RESET 2 start count Bits D[15:0]

> The contents of this register can be used to position the start of the ADC reset conversion. Refer to the Using the Timer Module section for details.



ADCRSTENDCT2: ADC Reset 2 End Count Register (Address = 1Ah, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ADCRSTE	NDCT2[15:0]		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	ADCRSTENDCT2[15:0]											

This register sets the end position of the ADC2 reset conversion signal.

Bits D[23:16] Must be '0'

Bits D[15:0] ADCRSTENDCT2[15:0]: ADC RESET 2 end count

The contents of this register can be used to position the end of the ADC reset conversion. Refer to the *Using the Timer Module* section for details.

ADCRSTSTCT3: ADC Reset 3 Start Count Register (Address = 1Bh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0		ADCRSTS	TCT3[15:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	ADCRSTSTCT3[15:0]										

This register sets the start position of the ADC3 reset conversion signal.

Bits D[23:16] Must be '0'

Bits D[15:0] ADCRSTSTCT3[15:0]: ADC RESET 3 start count

The contents of this register can be used to position the start of the ADC reset conversion. Refer to the *Using the Timer Module* section for details.

ADCRSTENDCT3: ADC Reset 3 End Count Register (Address = 1Ch, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		ADCRSTE	NDCT3[15:0]]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	ADCRSTENDCT3[15:0]											

This register sets the end position of the ADC3 reset conversion signal.

Bits D[23:16] Must be '0'

Bits D[15:0] ADCRSTENDCT3[15:0]: ADC RESET 3 end count

The contents of this register can be used to position the end of the ADC reset conversion signal (default value after reset is 0000h). Refer to the *Using the Timer Module* section for details.



DDCOLINT, Dulco	Donotition	Dariad Count	Dogistor (Address -	- 1Dh	Docot Value - 0000	h\

Р	RPCOUN	IT: Pulse	Repetitio	n Period	Count R	egister (Address :	= 1Dh, R	eset Valu	e = 0000h	ո)	
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	0	0		PRPCOL	JNT[15:0]		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	PRPCOUNT[15:0]											

This register sets the device pulse repetition period count.

Bits D[23:16] Must be '0'

Bits D[15:0] PRPCOUNT[15:0]: Pulse repetition period count

> The contents of this register can be used to set the pulse repetition period (in number of clock cycles of the 4-MHz clock).

CONTROL1: Control Register 1 (Address = 1Eh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Cl	KALMPIN[2	2:0]	TIMEREN								

This register configures the clock alarm pin, timer, and number of averages.

Bits D[23:12] Must be '0'

Bits D[11:9] CLKALMPIN[2:0]: Clocks on ALM pins

> Internal clocks can be brought to the PD_ALM and LED_ALM pins for monitoring. Note that the CLKALMPIN[2:0] register bits must be set before using this register bit.

Table 5 defines the settings for the two alarm pins.

Bit D8 **TIMEREN: Timer enable**

0 = Timer module is disabled and all internal clocks are off (default after reset)

1 = Timer module is enabled

Bits D[7:0] NUMAV[7:0]: Number of averages

Specify an 8-bit value corresponding to the number of ADC samples to be averaged - 1.

For example, to average four ADC samples, set NUMAV[7:0] equal to 3.

Table 5. PD_ALM and LED_ALM Pin Settings

CLKALMPIN[2:0]	PD_ALM PIN SIGNAL	LED_ALM PIN SIGNAL
000	Sample LED2	Sample LED1
001	LED2 pulse	LED1 pulse
010	Sample LED2	Sample LED1 pulse
011	LED2 convert	LED1 convert
100	LED2 ambient	LED1 ambient
101	No output	No output
110	No output	No output
111	No output	No output



SPARE1: SPARE1 Register For Future Use (Address = 1Fh, Reset Value = 0000h)

			_			•				-	
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	1	1	1	T	0		0	0	0	0

This register is a spare register and is reserved for future use.

Bits D[23:0] Must be '0'

TIAGAIN: Transimpedance Amplifier Gain Setting Register (Address = 20h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	ENSEP GAIN	0	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0		(CF_LED1[4:0		F	RF_LED1[2:0	0]	

This register sets the device transimpedance amplifier gain mode and feedback resistor and capacitor values.

Bits D[23:16] Must be '0'

Bit D15 ENSEPGAIN: Enable separate gain mode

 $0 = \text{The R}_F$ and C_F values are the same for both LED2 and LED1 signals; the value specified by the RF LED2[2:0] register bits is used (default after reset)

1 = The R_F value is different for the LED2 and LED1 signals; the values are specified by the

RF_LED1[2:0] and RF_LED2[2:0] register bits

Bits D[14:8] Must be '0'

Bits D[7:3] CF_LED1[4:0]: Program C_F for LED1

00000 = 5 pF (default after reset) 00100 = 25 pF + 5 pF 00001 = 5 pF + 5 pF 01000 = 50 pF + 5 pF 00010 = 15 pF + 5 pF 10000 = 150 pF + 5 pF

Note that any combination of these C_{F} settings is also supported by setting multiple bits to

'1'. For example, to obtain $C_F = 100 \text{ pF}$, set D[7:3] = 01111.

Bits D[2:0] RF LED1[2:0]: Program R_F for LED1

 $\begin{array}{lll} 000 = 500 \; k\Omega \; (\text{default after reset}) & 100 = 25 \; k\Omega \\ 001 = 250 \; k\Omega & 101 = 10 \; k\Omega \\ 010 = 100 \; k\Omega & 110 = 1 \; M\Omega \\ 011 = 50 \; k\Omega & 111 = \text{None} \end{array}$

TIA_AMB_GAIN: Transimpedance Amplifier and Ambient Cancellation Stage Gain Register (Address = 21h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0		AMBD	AC[3:0]		FLTR CNRSEL	STAGE2 EN	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	S.	TG2GAIN[2:	:0]		C	F_LED2[4:0	0]		R	F_LED2[2:	0]

This register configures the ambient light cancellation amplifier gain, cancellation current, and filter corner frequency.

Bits D[23:20] Must be '0'

Bits D[19:16] AMBDAC[3:0]: Ambient DAC value

These bits set the value of the cancellation current.

 $0000 = 0 \mu A$ (default after reset) $1000 = 8 \mu A$ $0001 = 1 \mu A$ $1001 = 9 \mu A$ $0010 = 2 \mu A$ $1010 = 10 \mu A$ $0011 = 3 \mu A$ 1011 = Do not use $0100 = 4 \mu A$ 1100 = Do not use $0101 = 5 \mu A$ 1101 = Do not use $0110 = 6 \mu A$ 1110 = Do not use $0111 = 7 \mu A$ 1111 = Do not use

Bit D15 FLTRCNRSEL: Filter corner selection

0 = 500-Hz filter corner (default after reset)

1 = 1000-Hz filter corner

Bit D14 STAGE2EN: Stage 2 enable

0 = Stage 2 is bypassed (default after reset)

1 = Stage 2 is enabled with the gain value specified by the STG2GAIN[2:0] bits

Bits D[13:11] Must be '0'

Bits D[10:8] STG2GAIN[2:0]: Stage 2 gain setting

000 = 0 dB, or linear gain of 1 (default after reset) 100 = 12 dB, or linear gain of 4 101 = Do not use

001 = 3 dB, or linear gain of 1.414 110 = Do not use 010 = 6 dB, or linear gain of 2 111 = Do not use

011 = 9 dB, or linear gain of 2.818

Bits D[7:3] CF_LED2[4:0]: Program C_F for LED2

00000 = 5 pF (default after reset) 00100 = 25 pF + 5 pF 00001 = 5 pF + 5 pF 01000 = 50 pF + 5 pF 00010 = 15 pF + 5 pF 10000 = 150 pF + 5 pF

Note that any combination of these C_F settings is also supported by setting multiple bits to '1'. For example, to obtain $C_F = 100$ pF, set D[7:3] = 01111.

Bits D[2:0] $RF_LED2[2:0]$: Program R_F for LED2

 $\begin{array}{lll} 000 = 500 \; k\Omega & 100 = 25 \; k\Omega \\ 001 = 250 \; k\Omega & 101 = 10 \; k\Omega \\ 010 = 100 \; k\Omega & 110 = 1 \; M\Omega \\ 011 = 50 \; k\Omega & 111 = None \end{array}$





	L	EDCNTR	RL: LED (Control R	egister (Address :	= 22h, Re	set Value	e = 0000h)	
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	LED_RA	NGE[1:0]		LED'	1[7:0]	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	LED'	1[7:0]					LED2	2[7:0]			

This register sets the LED current range and the LED1 and LED2 drive current.

Bits D[23:18] Must be '0'

LED_RANGE[1:0]: LED range Bits D[17:16]

These bits program the full-scale LED current range for Tx. Table 6 details the settings.

Bits D[15:8] LED1[7:0]: Program LED current for LED1 signal

> Use these register bits to specify the LED current setting for LED1 (default after reset is 00h).

The nominal value of the LED current is given by Equation 4,

where the full-scale LED current is either 0 mA, 50 mA, 75 mA, 100 mA, 150 mA, or 200 mA

(as specified by the LED_RANGE[1:0] register bits).

Bits D[7:0] LED2[7:0]: Program LED current for LED2 signal

> Use these register bits to specify the LED current setting for LED2 (default after reset is 00h).

The nominal value of LED current is given by Equation 5,

where the full-scale LED current is either 0 mA, 50 mA, 75 mA, 100 mA, 150 mA, or 200 mA (as specified by the LED RANGE[1:0] register bits).

Table 6. Full-Scale LED Current across Tx Reference Voltage Settings

LED DANCEIA.01	LED CURR	LED CURRENT RANGE FOR Tx REFERENCE VOLTAGE								
LED_RANGE[1:0]	0.75 V (TX_REF[1:0] = 00)	0.5 V (TX_REF[1:0] = 01)	1.0 V (TX_REF[1:0] = 10)							
00 (default after reset)	150 mA	100 mA	200 mA							
01	75 mA	50 mA	100 mA							
10	150 mA	100 mA	200 mA							
11	Tx is off	Tx is off	Tx is off							

LED1[7:0] × Full-Scale Current

(4)

× Full-Scale Current

(5)



CONTROL 2: Control Register 2 (Address = 23h, Reset Value = 0000h)

CONTROL2: Control Register 2 (Address = 23n, Reset Value = 0000n)												
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
0	0	0	0	0	0	TX_SUP_ 3V	0	EN_ADC _BYP	0	0	0	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
TXBRG MOD	0	XTAL DIS	EN_ SLOW_ DIAG	0	0	0	0	0	PDNTX	PDNRX	PDNAFE	

This register controls the LED transmitter, crystal, and the AFE, transmitter, and receiver power modes.

Bits D[23:19] Must be '0'

Bits D[18:17] TX_REF[1:0]: Tx reference voltage

These bits set the transmitter reference voltage. This Tx reference voltage is available on the device TX REF pin.

00 = 0.75-V Tx reference voltage (default value after reset)

01 = 0.5-V Tx reference voltage 10 = 1.0-V Tx reference voltage 11 = 0.75-V Tx reference voltage

Bit D16 Must be '0'

Bit D15 EN_ADC_BYP: ADC bypass mode enable

0 = Normal mode, the internal ADC is active (default after reset)

1 = ADC bypass mode, the analog signal is output to the ADC_BYPP and ADC_BYPN pins

Bits D[14:12] Must be '0'

Bit D11 TXBRGMOD: Tx bridge mode

0 = LED driver is configured as an H-bridge (default after reset)

1 = LED driver is configured as a push-pull

Bit D10 Must be '0'

Bit D9 XTALDIS: Crystal disable mode

0 = The crystal module is enabled; the 8-MHz crystal must be connected to the XIN and

XOUT pins

1 = The crystal module is disabled; an external 8-MHz clock must be applied to the XIN pin

Bit D8 EN SLOW DIAG: Fast diagnostics mode enable

0 = Fast diagnostics mode, 8 ms (default value after reset)

1 = Slow diagnostics mode, 16 ms

Bits D[7:3] Must be '0'

Bit D2 PDN_TX: Tx power-down

0 = The Tx is powered up (default after reset)1 = Only the Tx module is powered down

Bit D1 PDN_RX: Rx power-down

0 = The Rx is powered up (default after reset)1 = Only the Rx module is powered down

Bit D0 PDN_AFE: AFE power-down

0 = The AFE is powered up (default after reset)

1 = The entire AFE is powered down (including the Tx, Rx, and diagnostics blocks)



SPARE2: SPARE2 Register For Future Use (Address = 24h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
	_	_	_	_	_	_	_	_	_	_	_
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0

This register is a spare register and is reserved for future use.

Bits D[23:0] Must be '0'

SPARE3: SPARE3 Register For Future Use (Address = 25h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
		•			•				•		
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0

This register is a spare register and is reserved for future use.

Bits D[23:0] Must be '0'

SPARE4: SPARE4 Register For Future Use (Address = 26h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
				•						•	
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0

This register is a spare register and is reserved for future use.

Bits D[23:0] Must be '0'

RESERVED1: RESERVED1 Register For Factory Use Only (Address = 27h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0

This register is reserved for factory use. Readback values vary between devices.

Bits D[23:0] Must be '0'

RESERVED2: RESERVED2 Register For Factory Use Only (Address = 28h, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12
0	0	0	0	0	0	0	0	0	0	0	0
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0

This register is reserved for factory use. Readback values vary between devices.

Bits D[23:0] Must be '0'

D12 0



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		ALA	RM: Alar	m Regist	er (Addre	ess = 29h	, Reset V	alue = 00)00h)		
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	
0	0	0	0	0	0	0	0	0	0	0	Ī
D44	D40	DO	Do	D7	DC	Dr	D4	Do	Do	D4	

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This register controls the Alarm pin functionality.

Bits D[23:8] Must be '0'

Bit D7 ALMPINCLKEN: Alarm pin clock enable

0 = Disables the monitoring of internal clocks; the PD_ALM and LED_ALM pins function as diagnostic fault alarm output pins (default after reset)

1 = Enables the monitoring of internal clocks; these clocks can be brought out on PD_ALM and LED ALM selectively (depending on the value of the CLKALMPIN[2:0] register bits).

Bits D[6:0] Must be '0'

LED2VAL: LED2 Digital Sample Value Register (Address = 2Ah, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
LED2VAL[23:0] D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0												
• •												
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	LED2VAL[23:0]											

This register contains the digital value of the latest LED2 sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

Bits D[23:0] LED2VAL[23:0]: LED2 digital value

This register contains the digital value of the latest LED2 sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

ALED2VAL: Ambient LED2 Digital Sample Value Register (Address = 2Bh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
	ALED2VAL[23:0] D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0											
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	ALED2VAL[23:0]											

This register contains the digital value of the latest LED2 ambient sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

Bits D[23:0] ALED2VAL[23:0]: LED2 ambient digital value

This register contains the digital value of the latest LED2 ambient sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.



LED1VAL: LED1 Digital Sample Value Register (Address = 2Ch, Reset Value = 0000h)

			_	•	_	•		-		•		
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
					LED1V	AL[23:0]						
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	LED1VAL[23:0]											

This register contains the digital value of the latest LED1 sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

Bits D[23:0] LED1VAL[23:0]: LED1 digital value

This register contains the digital value of the latest LED1 sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

ALED1VAL: Ambient LED1 Digital Sample Value Register (Address = 2Dh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12		
	ALED1VAL[23:0]												
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0		
	ALED1VAL[23:0]												

This register contains the digital value of the latest LED1 ambient sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

Bits D[23:0] ALED1VAL[23:0]: LED1 ambient digital value

This register contains the digital value of the latest LED1 ambient sample converted by the ADC. The ADC_RDY signal goes high each time that the contents of this register are updated. The host processor must readout this register before the next sample is converted by the AFE.

LED2-ALED2VAL: LED2-Ambient LED2 Digital Sample Value Register (Address = 2Eh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
LED2-ALED2VAL[23:0] D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0												
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
	LED2-ALED2VAL[23:0]											

This register contains the digital value of the LED2 sample after the LED2 ambient is subtracted. The host processor must readout this register before the next sample is converted by the AFE.

Bits D[23:0] LED2-ALED2VAL[23:0]: (LED2 – LED2 ambient) digital value

This register contains the digital value of the LED2 sample after the LED2 ambient is subtracted. The host processor must readout this register before the next sample is converted by the AFE.

LED1-ALED1VAL: LED1-Ambient LED1 Digital Sample Value Register (Address = 2Fh, Reset Value = 0000h)

D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	
	LED1-ALED1VAL[23:0]											
D11												
	LED1-ALED1VAL[23:0]											

This register contains the digital value of the LED1 sample after the LED1 ambient is subtracted. The host processor must readout this register before the next sample is converted by the AFE.

Bits D[23:0] LED1-ALED1VAL[23:0]: (LED1 – LED1 ambient) digital value

This register contains the digital value of the LED1 sample after the LED1 ambient is subtracted from it. The host processor must readout this register before the next sample is converted by the AFE.



	DIAG: Diagnostics Flag Register (Address = 30h, Reset Value = 0000h)													
D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12			
0	0	0	0	0	0	0	0	0	0	0	PD_ALM			
D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0			
LED_ ALM	LED1 OPEN	LED2 OPEN	LEDSC	OUTPSH GND	OUTNSH GND	PDOC	PDSC	INNSC GND	INPSC GND	INNSC LED	INPSC LED			

This register is read only. This register contains the status of all diagnostic flags at the end of the diagnostics sequence. The end of the diagnostics sequence is indicated by the signal going high on DIAG_END pin.

Bits D[23:13] Read only

Bit D12 PD_ALM: Power-down alarm status diagnostic flag

This bit indicates the status of PD_ALM (and the PD_ALM pin).

0 = No fault (default after reset)

1 = Fault present

Bit D11 LED_ALM: LED alarm status diagnostic flag

This bit indicates the status of LED_ALM (and the LED_ALM pin).

0 = No fault (default after reset)

1 = Fault present

Bit D10 LED1OPEN: LED1 open diagnostic flag

This bit indicates that LED1 is open. 0 = No fault (default after reset)

1 = Fault present

Bit D9 LED2OPEN: LED2 open diagnostic flag

This bit indicates that LED2 is open. 0 = No fault (default after reset)

1 = Fault present

Bit D8 LEDSC: LED short diagnostic flag

This bit indicates an LED short. 0 = No fault (default after reset)

1 = Fault present

Bit D7 OUTPSHGND: OUTP to GND diagnostic flag

This bit indicates that OUTP is shorted to the GND cable.

0 = No fault (default after reset)

1 = Fault present

Bit D6 OUTNSHGND: OUTN to GND diagnostic flag

This bit indicates that OUTN is shorted to the GND cable.

0 = No fault (default after reset)

1 = Fault present

Bit D5 PDOC: PD open diagnostic flag

This bit indicates that PD is open. 0 = No fault (default after reset)

1 = Fault present

Bit D4 PDSC: PD short diagnostic flag

This bit indicates a PD short. 0 = No fault (default after reset)

1 = Fault present



Bit D3 INNSCGND: INN to GND diagnostic flag

This bit indicates a short from the INN pin to the GND cable.

0 = No fault (default after reset)

1 = Fault present

Bit D2 INPSCGND: INP to GND diagnostic flag

This bit indicates a short from the INP pin to the GND cable.

0 = No fault (default after reset)

1 = Fault present

Bit D1 INNSCLED: INN to LED diagnostic flag

This bit indicates a short from the INN pin to the LED cable.

0 = No fault (default after reset)

1 = Fault present

INPSCLED: INP to LED diagnostic flag Bit D0

This bit indicates a short from the INP pin to the LED cable.

0 = No fault (default after reset)

1 = Fault present

Product Folder Links: AFE4490

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22-Feb-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
AFE4490RHAR	ACTIVE	VQFN	RHA	40	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70		Samples
AFE4490RHAT	ACTIVE	VQFN	RHA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

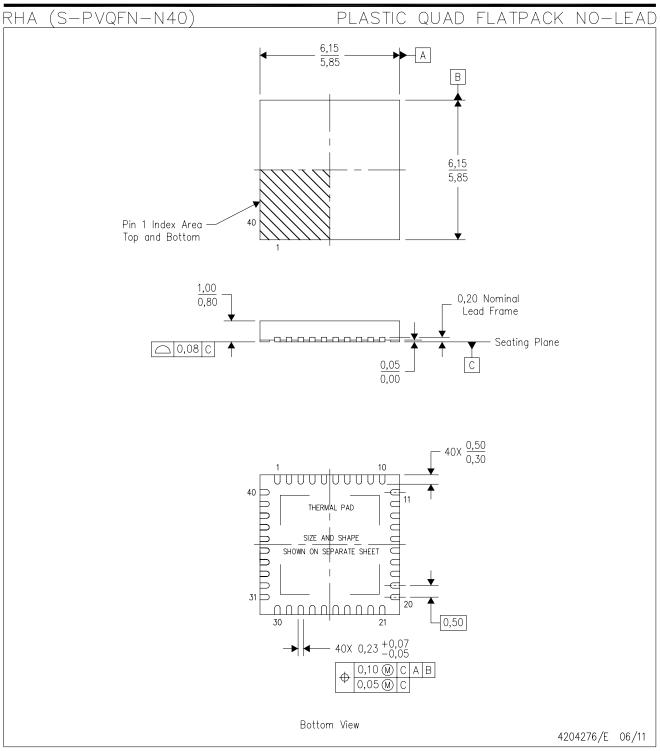
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.



- NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) Package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Package complies to JEDEC MO-220 variation VJJD-2.



RHA (S-PVQFN-N40)

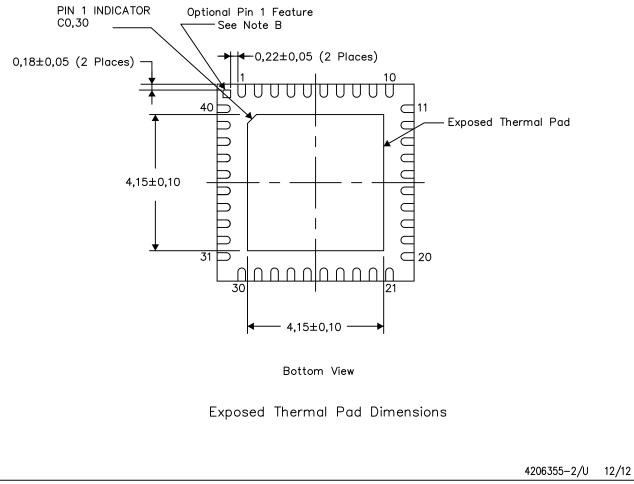
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



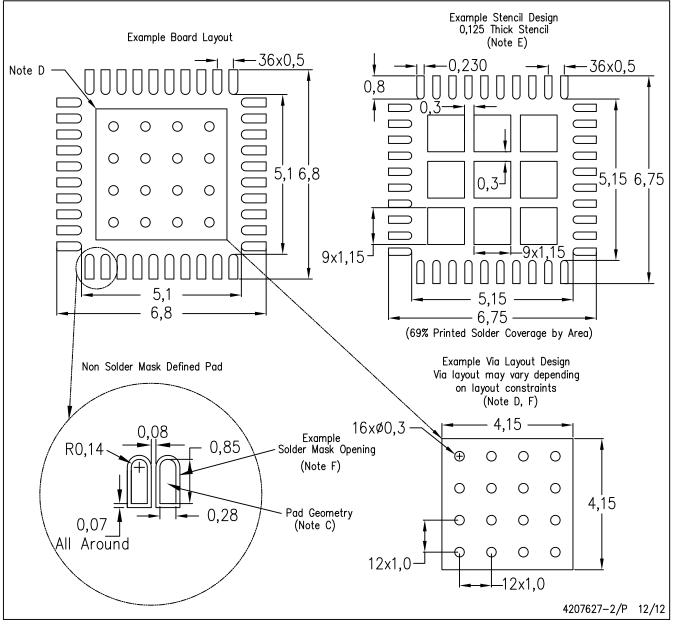
NOTES: A. All linear dimensions are in millimeters

B. The Pin 1 Identification mark is an optional feature that may be present on some devices In addition, this Pin 1 feature if present is electrically connected to the center thermal pad and therefore should be considered when routing the board layout.



RHA (S-PVQFN-N40)

PLASTIC QUAD FLATPACK NO-LEAD



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat—Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com http://www.ti.com>.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.



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